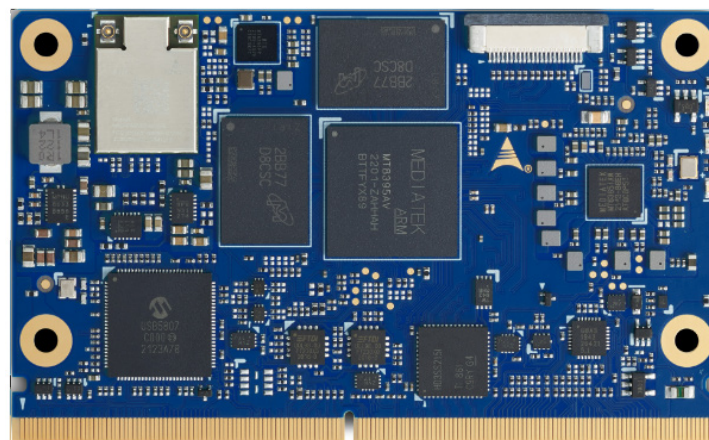


LEC-MTK-I1200

User's Guide

Powered by
MediaTek



Revision: Rev. 1.1
Date: 2025-11-04
Part Number: 50M-72516-1010



Revision History

Revision	Description	Date	Author
1.0	Initial release	2025-11-23	CC
1.1	Specifications updated	2025-11-04	AL

Preface

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For user safety, please read and follow all Instructions, WARNINGS, CAUTIONs, and NOTEs marked in this manual and on the associated equipment before handling/operating the equipment.

Read these safety instructions carefully.

- Keep this manual for future reference.
- Read the specifications section of this manual for detailed information on the operating environment of this equipment.
- Turn off power and unplug any power cords/cables when installing/mounting or un-installing/removing equipment.
- To avoid electrical shock and/or damage to equipment:
- Keep equipment away from water or liquid sources;
- Keep equipment away from high heat or high humidity;
- Keep equipment properly ventilated (do not block or cover ventilation openings);
- Make sure to use recommended voltage and power source settings;
- Always install and operate equipment near an easily accessible electrical socket outlet;
- Secure the power cord (do not place any object on/over the power cord);
- Only install/attach and operate equipment on stable surfaces and/or recommended mountings;
- If the equipment will not be used for long periods of time, turn off the power source and unplug the equipment.

Conventions

The following conventions may be used throughout this manual, denoting special levels of information



Note: This information adds clarity or specifics to text and illustrations.



Caution: This information indicates the possibility of minor physical injury, component damage, data loss, and/or program corruption.



Warning: This information warns of possible serious physical injury, component damage, data loss, and/or program corruption.

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Table of Contents

Revision History	2
Preface	3
1. Introduction	10
1.1 LEC-MTK-i1200	10
1.2 The SMARC Form Factor	10
2. Specifications	11
2.1 Core System	11
2.2 Video	12
2.2.1 GPU / VPU	12
2.2.2 Display Interfaces	13
2.3 Camera	13
2.4 Audio	13
2.5 Dual Ethernet	14
2.6 Wi-Fi / Bluetooth	14
2.7 Extension Buses	14
2.8 System Storage	15
2.9 Board Controller	16
2.10 Debug Header DB30	16
2.11 Fan Control	16
2.12 Power	16
2.13 Mechanical and Environmental	17
3. Block Diagram	18
4. Pinout and Signal Descriptions	19
4.1 Pin Summary	19
4.2 Signal Terminology Descriptions	23
4.3 Signal Description by Function	24
4.3.1 Primary Display Interface	24
4.4 Secondary Display Interface	28
4.4.2 MIPI Camera Support	30
4.4.3 I ² S (Audio)	32
4.4.4 USB ports	33
4.4.5 LAN Ports	37

4.4.6	SDIO.....	39
4.4.7	SPI.....	40
4.4.8	GPIO.....	41
4.4.9	CAN Bus.....	42
4.4.10	Miscellaneous.....	42
4.4.11	Power and System Management.....	43
4.4.12	Boot Select.....	45
4.4.13	Power.....	46
4.5	SMARC Pin-to-controller Mapping.....	47
5.	Software Support.....	58
5.1	Yocto.....	58
5.2	Android.....	58
5.3	AI.....	58
6.	Mechanical.....	59
7.	Thermal Solutions.....	60
7.1	Heatspreader: HTS.....	60
7.2	Heatsink: THS.....	61
Revision History.....		2
Preface.....		3
1.	Introduction.....	10
1.1	LEC-MTK-i1200.....	10
1.2	The SMARC Form Factor.....	10
2.	Specifications.....	11
2.1	Core System.....	11
2.2	Video.....	12
2.2.1	GPU / VPU.....	12
2.2.2	Display Interfaces.....	13
2.3	Camera.....	13
2.4	Audio.....	13
2.5	Dual Ethernet.....	14
2.6	Wi-Fi / Bluetooth.....	14
2.7	Extension Buses.....	14

2.8	System Storage	15
2.9	Board Controller.....	16
2.10	Debug Header DB30.....	16
2.11	Fan Control.....	16
2.12	Power.....	16
2.13	Mechanical and Environmental	17
3.	Block Diagram	18
4.	Pinout and Signal Descriptions	19
4.1	Pin Summary	19
4.2	Signal Terminology Descriptions.....	23
4.3	Signal Description by Function.....	24
4.3.1	Primary Display Interface.....	24
4.4	Secondary Display Interface.....	28
4.4.2	MIPI Camera Support.....	30
4.4.3	I ² S (Audio)	32
4.4.4	USB ports.....	33
4.4.5	LAN Ports.....	37
4.4.6	SDIO.....	39
4.4.7	SPI.....	40
4.4.8	GPIO.....	41
4.4.9	CAN Bus	42
4.4.10	Miscellaneous	42
4.4.11	Power and System Management	43
4.4.12	Boot Select.....	45
4.4.13	Power	46
4.5	SMARC Pin-to-controller Mapping.....	47
5.	Software Support	58
5.1	Yocto.....	58
5.2	Android	58
5.3	AI	58
6.	Mechanical.....	59
7.	Thermal Solutions.....	60
7.1	Heatspreader: HTS	60
7.2	Heatsink: THS	61

List of Figures

Figure 1 – Module function diagram.....18

Figure 2 – Module top/botom side pin numbering19

Figure 3 – Module Dimensions.....59

Figure 4 – Heatspreader HTS.....60

Figure 5 – Heatsink THS.....61

1. Introduction

1.1 LEC-MTK-i1200

ADLINK LEC-MTK-i1200 is a SMARC module based on MediaTek Genio 1200 (4x Arm Cortex-A78 + 4x Cortex-A55) processor with up to 5 TOPS AI Processor Unit (APU). The module incorporates a spate of IoT technologies, such as on-device artificial intelligence (AI) capabilities and up to 3 camera support while delivering a low power envelope, making it the ideal solution for robotic and drone applications across various sectors, including consumer, enterprise, defense, industrial, logistics, and more.

1.2 The SMARC Form Factor

The SMARC ("Smart Mobility ARChitecture") is a versatile small form factor Computer on Module definition targeting applications that require low power and high performance at low costs. Typically under 6W, the modules often utilize ARM and other alternative low-power option CPUs, and are used in many familiar handheld devices, such as tablet computers and smart phones.

Two module sizes are defined in SMARC: 82 mm x 50 mm and 82 mm x 80 mm.

The module PCBs have 314 edge fingers that mate with a low-profile 314 pin 0.5 mm pitch right angle connector (the connector is sometimes identified as a 321 pin connector, with 7 pins used by the key).

SMARC modules are used as building blocks for portable and stationary embedded systems. The core CPU and support circuits, including DRAM, boot flash, power sequencing, CPU power supplies, GBE and a single channel LVDS display transmitter are concentrated on the module. Modules are used with application-specific carrier boards that implement other features such as audio codecs, touch controllers, wireless devices, etc.

The modular approach allows scalability, faster time to market and upgradability while still maintaining low costs, low power, and small physical size.



SMARC module and carrier specifications are available online at: <https://www.sget.org/standards/smarc.html>



Note: This module is compliant with the new 2.1.1 pinout.

2. Specifications

2.1 Core System

SoC

MediaTek Genio i1200 8-core CPU:

- 4x Arm Cortex-A78 (64KB L1 per core) + 4x Cortex-A55 (32KB L1 per core)

AI Accelerator

Top performance:

- Fix8 1966 GMACs, Fix16 983 GMACs, FP16 983 GMACs
- Supports Android NN asymmetric quantized data format
- Supports compressed weight to reduce DRAM BW

Memory

LPDDR4X SDRAM @2133MHz supporting up to 16GB system memory down

L2 Cache

System L2 cache (ECC), 256KB/core for Cortex-A78, 128KB per core for Cotex-A55

L3 Cache

Shared 2MB L3 cache

Security

Arm TrustZone security, TPM 2.0 (optional)

2.2 Video

2.2.1 GPU / VPU

GPU Core

MALI G57 MC5 supporting 4K60

VPU Core

4x video data processing pipe (SVPP), 2x hard warping engine

Each video data processing pipe supports:

- HDR decode/encode/transcode, HDR10, DHR10+, HLG.
- Auto local contrast enhancement
- Image resizer, scaling ratio range 1/128 to 64
- Image sharpening
- Preference color tuning

Graphics

- 3D graphic accelerator capable of processing 17600M pixel/sec @880MHz
- OpenGL ES 3.2/2.0/1.1
- Vulkan 1.1/1.0
- OpenCL 2.2

2.2.2 Display Interfaces

MIPI DSI

2x MIPI DSI 4 lane, compliant with MIPI-DSI standard v1.2, max. resolution 4K p60

eDP

1x 4lane eDP port

HDMI

HDMI 2.0b , Supports a maximum display resolution of 4K p60

DP

Displayport 1.4, 4K p60

2.3 Camera

Supports CSI0 2-lane and CSI1 4-lane MIPI CSI2 camera input over MXM connector.

CSI2 on module feature connector (4 lanes)

2.4 Audio

Supports on-carrier I²S codec

2.5 Dual Ethernet

Primary LAN

10/100/1000 Ethernet controller over RGMII with PHY

Supports 10/100/1000-Mbps data transfer rates, both full-duplex and half-duplex

Secondary LAN

10/100/1000 Ethernet controller over USB 3.0

Supports 10/100/1000-Mbps data transfer rates, both full-duplex and half-duplex

2.6 Wi-Fi / Bluetooth

M.2 1216 industry standard footprint with support for PCIe solder down modules

2.7 Extension Buses

PCIe

1x PCI Express Gen3 x1/x, 1x PCI Express Gen2 x1

USB

2x USB 3.0/2.0, 2x USB 2.0 coming from USB hub, 2 x USB 2.0 coming from SoC

UART

4x UART interfaces SER0,1,2,3 (SER2 derives from USB2UART)

CAN bus

1x CAN2.0B only or mixed CAN2.0B and CAN FD mode, data bit rate up to 8 Mbps (over SPI optional)

SPI

2x SPI

I²S

1x I²S

I²C

4x I²C

Software programmable clock frequency:

- Standard mode: 100 kbit/s
- Fast mode: 400 kbit/s

GPIO

14 x GPIO with interrupt, one GPIO with PWM

2.8 System Storage

SDIO

1x SDIO (4-bit) compatible with SD3.0, MMC version 4.51 to edge connector

UFS Storage

Up to 256GB UFS

2.9 Board Controller

BMC lite for power sequence

SEMA BMC Error Code

Exception Code	Error Code
0	NOERROR
2	NO_VIN
3	NO_SDM_RESIN_N
4	NO_SDM_RESIN_N

2.10 Debug Header DB30

Multipurpose Connector: ADLINK standard 30-pin FPC with following pins

- Boot Select strap pins
- Serial port

2.11 Fan Control

Passive cooling, no fan control pins

2.12 Power

5.0V +/- 5%

2.13 Mechanical and Environmental

Operating Temperature

Standard:	0 to 60°C	commercial grade BOM (memory, eMMC, USB hub, SoC)
Rugged:	-40 to 85°C	industrial grade BOM (memory, eMMC, USB hub, SoC, TBD)

Humidity

5-90% RH operating, non-condensing
5-95% RH storage (and operating with conformal coating)

EMI

EN55022 Class B inside an enclosure

Shock and Vibration

MIL-STD-202F, Method 213B, Table 213-I, Condition A.
MIL-STD-202F, Method 214A, Table 214-I, Condition D.

MTBF

300,000 hrs (at 40°C), 100,000 hrs (at 85°C),

3. Block Diagram

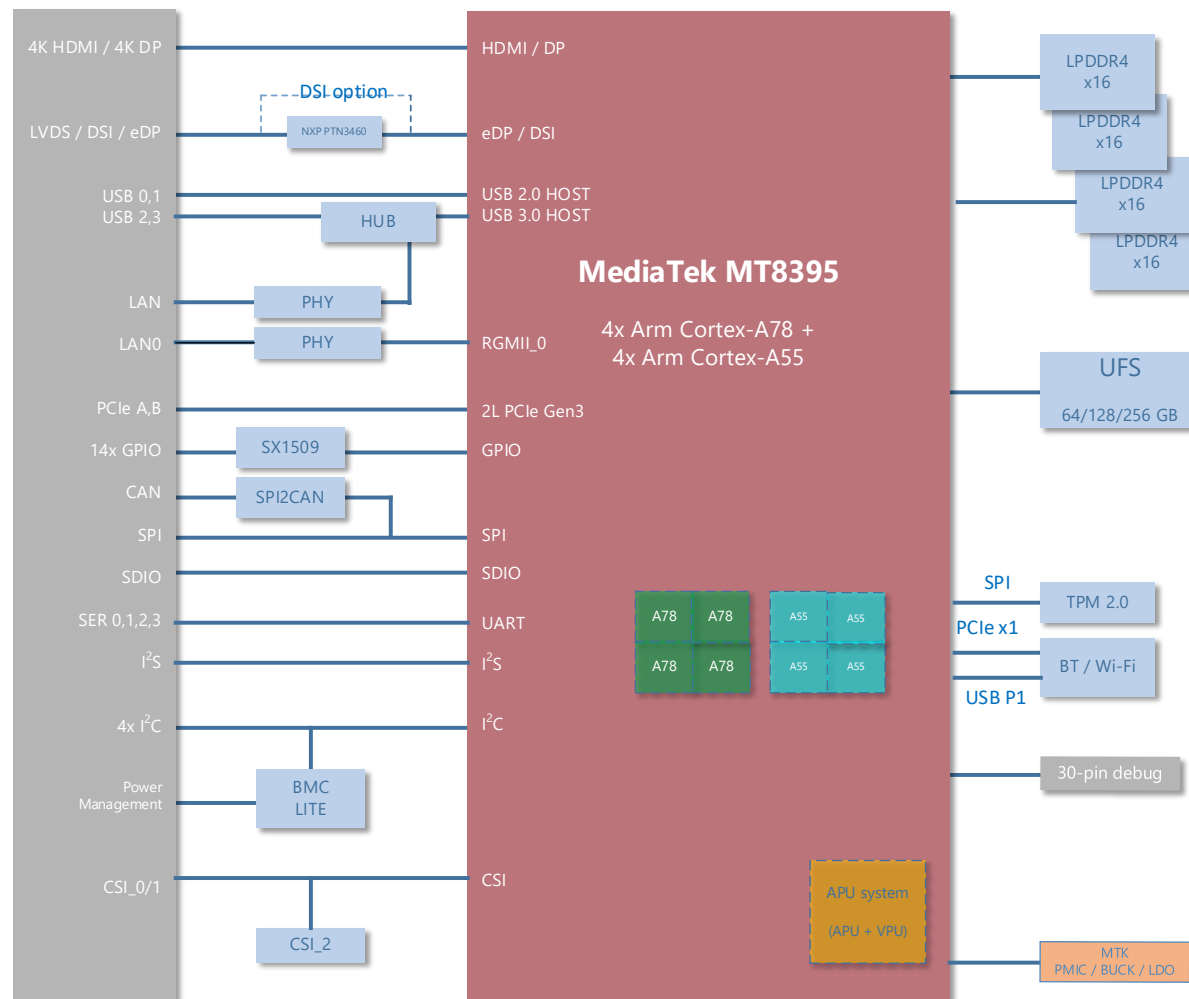


Figure 1 – Module function diagram

4. Pinout and Signal Descriptions

4.1 Pin Summary

The below table is a comprehensible list of all signal pins on the MXM 3 connector in the standard specification SMARC 2.1.

Signals not supported on LEC-MTK-i1200 are strikethrough ~~STRIKETHROUGH~~

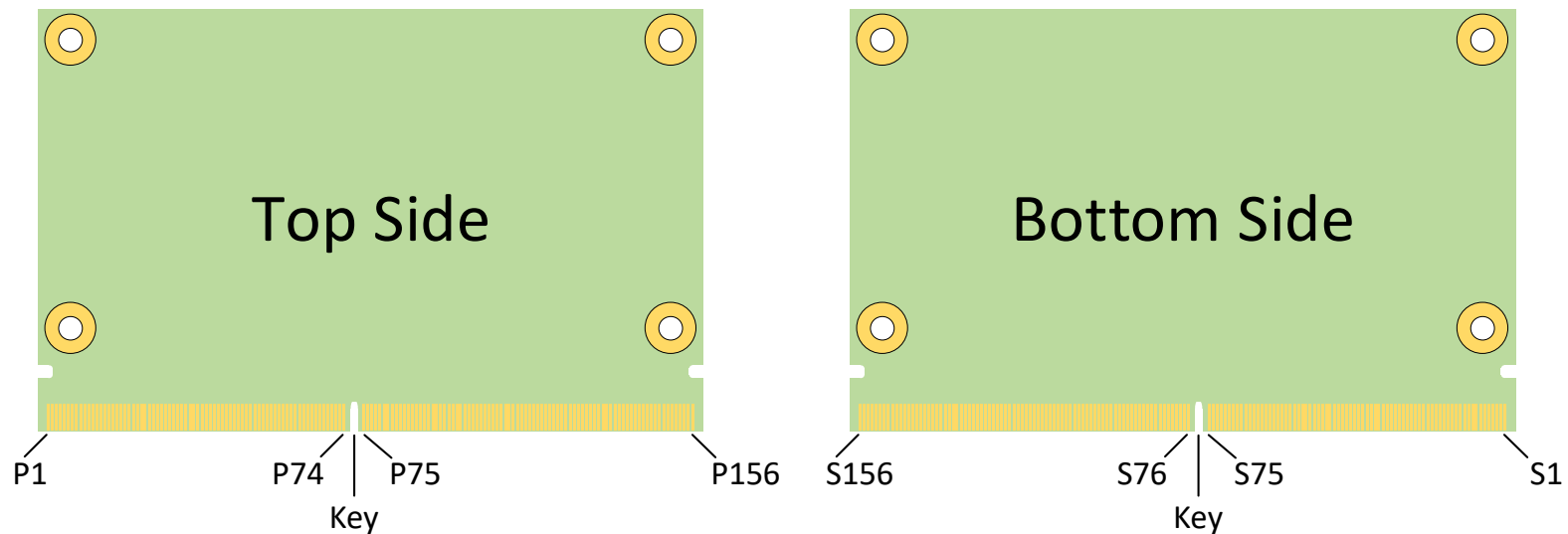


Figure 2 – Module top/bottom side pin numbering

P-Pin	Primary (Top) Side
P1	SMB_ALERT_1V8#
P2	GND
P3	CSI1_CK+
P4	CSI1_CK-
P5	GBE1_SDP
P6	GBE0_SDP
P7	CSI1_RX0+
P8	CSI1_RX0-
P9	GND
P10	CSI1_RX1+
P11	CSI1_RX1-
P12	GND
P13	CSI1_RX2+
P14	CSI1_RX2-
P15	GND
P16	CSI1_RX3+
P17	CSI1_RX3-
P18	GND
P19	GBE0_MDI3-
P20	GBE0_MDI3+
P21	GBE0_LINK100#
P22	GBE0_LINK1000#
P23	GBE0_MDI2-
P24	GBE0_MDI2+
P25	GBE0_LINK_ACT#
P26	GBE0_MDI1-
P27	GBE0_MDI1+
P28	GBE0_CTREF
P29	GBE0_MDI0-
P30	GBE0_MDI0+
P31	SPI0_CS1#
P32	GND
P33	SDIO_WP
P34	SDIO_CMD
P35	SDIO_CD#

S-Pin	Secondary (Bottom) Side
S1	CSI1_TX+ / I2C_CAM1_CK
S2	CSI1_TX- / I2C_CAM1_DAT
S3	GND
S4	RSVD
S5	CSI0_TX- / I2C_CAM0_CK
S6	CAM_MCK
S7	CSI0_TX+ / I2C_CAM0_DAT
S8	CSI0_CK+
S9	CSI0_CK-
S10	GND
S11	CSI0_RX0+
S12	CSI0_RX0-
S13	GND
S14	CSI0_RX1+
S15	CSI0_RX1-
S16	GND
S17	GBE1_MDI0+
S18	GBE1_MDI0-
S19	GBE1_LINK100#
S20	GBE1_MDI1+
S21	GBE1_MDI1-
S22	GBE1_LINK1000#
S23	GBE1_MDI2+
S24	GBE1_MDI2-
S25	GND
S26	GBE1_MDI3+
S27	GBE1_MDI3-
S28	GBE1_CTREF
S29	PCIE_D_TX+ /
S30	PCIE_D_TX- / SERDES_1_TX-
S31	GBE1_LINK_ACT#
S32	PCIE_D_RX+ /
S33	PCIE_D_RX- /
S34	GND
S35	USB4+

P-Pin	Primary (Top) Side
P36	SDIO_CK
P37	SDIO_PWR_EN
P38	GND
P39	SDIO_D0
P40	SDIO_D1
P41	SDIO_D2
P42	SDIO_D3
P43	SPI0_CS0#
P44	SPI0_CK
P45	SPI0_DIN
P46	SPI0_DO
P47	GND
P48	SATA_TX+
P49	SATA_TX-
P50	GND
P51	SATA_RX+
P52	SATA_RX-
P53	GND
P54	ESPI_CS0# / SPI1_CS0#
P55	ESPI_CS1# / SPI1_CS1#
P56	ESPI_CK / SPI1_CK
P57	ESPI_IO_1 / SPI1_DIN
P58	ESPI_IO_0 / SPI1_DO
P59	GND
P60	USB0+
P61	USB0-
P62	USB0_EN_OC#
P63	USB0_VBUS_DET
P64	USB0_OTG_ID
P65	USB1+
P66	USB1-
P67	USB1_EN_OC#
P68	GND
P69	USB2+
P70	USB2-

S-Pin	Secondary (Bottom) Side
S36	USB4-
S37	USB3_VBUS_DET
S38	AUDIO_MCK
S39	I2S0_LRCK
S40	I2S0_SDOUT
S41	I2S0_SDIN
S42	I2S0_CK
S43	ESPI_ALERT0#
S44	ESPI_ALERT1#
S45	MDIO_CLK
S46	MDIO_DAT
S47	GND
S48	I2C_GP_CK
S49	I2C_GP_DAT
S50	HDA_SYNC / I2S2_LRCK
S51	HDA_SDO / I2S2_SDOUT
S52	HDA_SDI / I2S2_SDIN
S53	HDA_CK / I2S2_CK
S54	SATA_ACT#
S55	USB5_EN_OC#
S56	ESPI_IO_2
S57	ESPI_IO_3
S58	ESPI_RESET#
S59	USB5+
S60	USB5-
S61	GND
S62	USB3_SSTX+
S63	USB3_SSTX-
S64	GND
S65	USB3_SSRX+
S66	USB3_SSRX-
S67	GND
S68	USB3+
S69	USB3-
S70	GND

P-Pin	Primary (Top) Side
P71	USB2_EN_OC#
P72	RSVD
P73	RSVD
P74	USB3_EN_OC#
	Key
P75	PCIE_A_RST#
P76	USB4_EN_OC#
P77	PCIE_B_CKREQ#
P78	PCIE_A_CKREQ#
P79	GND
P80	PCIE_C_REFCK+
P81	PCIE_C_REFCK-
P82	GND
P83	PCIE_A_REFCK+
P84	PCIE_A_REFCK-
P85	GND
P86	PCIE_A_RX+
P87	PCIE_A_RX-
P88	GND
P89	PCIE_A_TX+
P90	PCIE_A_TX-
P91	GND
P92	HDMI_D2+ / DP1_LANE0+
P93	HDMI_D2- / DP1_LANE0-
P94	GND
P95	HDMI_D1+ / DP1_LANE1+
P96	HDMI_D1- / DP1_LANE1-
P97	GND
P98	HDMI_D0+ / DP1_LANE2+
P99	HDMI_D0- / DP1_LANE2-
P100	GND
P101	HDMI_CK+ / DP1_LANE3+
P102	HDMI_CK- / DP1_LANE3-

S-Pin	Secondary (Bottom) Side
S71	USB2_SSTX+
S72	USB2_SSTX-
S73	GND
S74	USB2_SSRX+
S75	USB2_SSRX-
	Key
S76	PCIE_B_RST#
S77	PCIE_C_RST#
S78	PCIE_C_RX+ /
S79	PCIE_C_RX- / SERDES_2_RX-
S80	GND
S81	PCIE_C_TX+ /
S82	PCIE_C_TX- / SERDES_2_TX-
S83	GND
S84	PCIE_B_REFCK+
S85	PCIE_B_REFCK-
S86	GND
S87	PCIE_B_RX+
S88	PCIE_B_RX-
S89	GND
S90	PCIE_B_TX+
S91	PCIE_B_TX-
S92	GND
S93	DP0_LANE0+
S94	DP0_LANE0-
S95	DP0_AUX_SEL
S96	DP0_LANE1+
S97	DP0_LANE1-
S98	DP0_HPD
S99	DP0_LANE2+
S100	DP0_LANE2-
S101	GND
S102	DP0_LANE3+

P-Pin	Primary (Top) Side
P103	GND
P104	HDMI_HPD / DP1_HPD
P105	HDMI_CTRL_CK / DP1_AUX+
P106	HDMI_CTRL_DAT / DP1_AUX-
P107	DP1_AUX_SEL
P108	GPIO0 / CAM0_PWR#
P109	GPIO1 / CAM1_PWR#
P110	GPIO2 / CAM0_RST#
P111	GPIO3 / CAM1_RST#
P112	GPIO4 / HDA_RST#
P113	GPIO5 / PWM_OUT
P114	GPIO6 / TACHIN
P115	GPIO7
P116	GPIO8
P117	GPIO9
P118	GPIO10
P119	GPIO11
P120	GND
P121	I2C_PM_CK
P122	I2C_PM_DAT
P123	BOOT_SEL0#
P124	BOOT_SEL1#
P125	BOOT_SEL2#
P126	RESET_OUT#
P127	RESET_IN#
P128	POWER_BTN#
P129	SER0_TX
P130	SER0_RX
P131	SER0_RTS#
P132	SER0_CTS#
P133	GND
P134	SER1_TX
P135	SER1_RX
P136	SER2_TX
P137	SER2_RX

S-Pin	Secondary (Bottom) Side
S103	DP0_LANE3-
S104	USB3_OTG_ID
S105	DP0_AUX+
S106	DP0_AUX-
S107	LCD1_BKLT_EN
S108	LVDS1_CK+ / DSI1_CLK+
S109	LVDS1_CK- / DSI1_CLK-
S110	GND
S111	LVDS1_0+ / eDP1_TX0+ /
S112	LVDS1_0- / eDP1_TX0- /
S113	eDP1_HPD / DSI1_TE
S114	LVDS1_1+ / eDP1_TX1+ /
S115	LVDS1_1- / eDP1_TX1- /
S116	LCD1_VDD_EN
S117	LVDS1_2+ / eDP1_TX2+ /
S118	LVDS1_2- / eDP1_TX2- /
S119	GND
S120	LVDS1_3+ / eDP1_TX3+ /
S121	LVDS1_3- / eDP1_TX3- /
S122	LCD1_BKLT_PWM
S123	GPIO13
S124	GND
S125	LVDS0_0+ / eDP0_TX0+ /
S126	LVDS0_0- / eDP0_TX0- /
S127	LCD0_BKLT_EN
S128	LVDS0_1+ / eDP0_TX1+ /
S129	LVDS0_1- / eDP0_TX1- /
S130	GND
S131	LVDS0_2+/eDP0_TX2+/
S132	LVDS0_2- / eDP0_TX2- /
S133	LCD0_VDD_EN
S134	LVDS0_CK+/eDP0_AUX/
S135	LVDS0_CK-/eDP0_AUX-/
S136	GND
S137	LVDS0_3+ / eDP0_TX3+ /

P-Pin	Primary (Top) Side
P138	SER2_RTS#
P139	SER2_CTS#
P140	SER3_TX
P141	SER3_RX
P142	GND
P143	CAN0_TX
P144	CAN0_RX
P145	CAN1_TX
P146	CAN1_RX
P147	VDD_IN
P148	VDD_IN

S-Pin	Secondary (Bottom) Side
S138	LVDS0_3- / eDP0_TX3- /
S139	I2C_LCD_CK
S140	I2C_LCD_DAT
S141	LCD0_BKLT_PWM
S142	GPIO12
S143	GND
S144	eDP0_HPD / DSI0_TE
S145	WDT_TIME_OUT#
S146	PCIE_WAKE#
S147	VDD_RTC
S148	LID#

P-Pin	Primary (Top) Side
P149	VDD_IN
P150	VDD_IN
P151	VDD_IN
P152	VDD_IN
P153	VDD_IN
P154	VDD_IN
P155	VDD_IN
P156	VDD_IN

S-Pin	Secondary (Bottom) Side
S149	SLEEP#
S150	VIN_PWR_BAD#
S151	CHARGING#
S152	CHARGER_PRSENT#
S153	CARRIER_STBY#
S154	CARRIER_PWR_ON
S155	FORCE_RECOV#
S156	BATLOW#
S157	TEST#
S158	GND

4.2 Signal Terminology Descriptions

Meaning of the terms used for signal description tables. Signals described in the specification but not supported on the LEC-iMX8M Plus are marked with strikethrough STRIKETHROUGH

Term	Description
I	Input to the Module
O	Output from the Module
I/O	Bi-directional input/output
OD	Open drain
PU	PU (pull-up) resistor
PD	PD (pull-down) resistor
CMOS	Logic input or output
GBE MDI	Differential analogue signalling for gigabit media dependent interface
DP	Low voltage differential signal for DisplayPort interface
D-PHY	Low voltage differential signal for MIPI CSI-2 cameras and DSI displays
M-PHY	Low voltage differential signal for MIPI CSI-3 cameras
LVDS	Low voltage differential signal for LCD displays
PCIE	Low voltage differential signal for PCIe
SATA	Low voltage differential signal for SATA
TMDS HDMI	Transition minimized differential signal for HDMI displays
USB	DC coupled differential signalling for traditional (non-Superspeed) USB signals
USB SS	Differential signal for SuperSpeed USB signals
USB VBUS 5V	5V tolerant input for USB VBUS detection
VDD_IN	Main power source from Carrier to Module
3.3V	3.3V power domain: Active while CARRIER_PWRON is high and CARRIER_SBY# is NOT active (i.e. both signals are high)
1.8V	1.8V power domain: Active while CARRIER_PWRON is high and CARRIER_SBY# is NOT active (i.e. both signals are high)
3.3Vsb	3.3V standby power domain: Active while CARRIER_PWRON is high (regardless of CARRIER_SBY#)
1.8Vsb	1.8V standby power domain: Active while CARRIER_PWRON is high (regardless of CARRIER_SBY#)
Sleep	Module is in its lowest power state
Runtime	Module is full on. CARRIER_PWRON is high and CARRIER_SBY# is NOT active (i.e. both signals are high)
Standby	Module is in standby state or higher

4.3 Signal Description by Function

4.3.1 Primary Display Interface

HDMI, eDP, DP and DSI are all supported on this module

Pin #	LVDS Name	MIPI DSI Name	eDP Name
S125	LVDS0_0+	DSI0_D0+	eDP0_TX0+
S126	LVDS0_0-	DSI0_D0-	eDP0_TX0-
S128	LVDS0_1+	DSI0_D1+	eDP0_TX1+
S129	LVDS0_1-	DSI0_D1-	eDP0_TX1-
S131	LVDS0_2+	DSI0_D2+	eDP0_TX2+
S132	LVDS0_2-	DSI0_D2-	eDP0_TX2-
S137	LVDS0_3+	DSI0_D3+	eDP0_TX3+
S138	LVDS0_3-	DSI0_D3-	eDP0_TX3-
S134	LVDS0_CLK+	DSI0_CLK+	eDP0_AUX+
S135	LVDS0_CLK-	DSI0_CLK-	eDP0_AUX-
S133	LCD0_VDD_EN	LCD0_VDD_EN	LCD0_VDD_EN
S127	LCD0_BKLT_EN	LCD0_BKLT_EN	LCD0_BKLT_EN
S141	LCD0_BKLT_PWM	LCD0_BKLT_PWM	LCD0_BKLT_PWM
S144		DSI0_TE	eDP0_HPD

Pin #	LVDS Name	MIPI DSI Name	eDP Name
S111	LVDS1_0+	DSI1_D0+	eDP1_TX0+
S112	LVDS1_0-	DSI1_D0-	eDP1_TX0-
S114	LVDS1_1+	DSI1_D1+	eDP1_TX1+
S115	LVDS1_1-	DSI1_D1-	eDP1_TX1-
S117	LVDS1_2+	DSI1_D2+	eDP1_TX2+
S118	LVDS1_2-	DSI1_D2-	eDP1_TX2-
S120	LVDS1_3+	DSI1_D3+	eDP1_TX3+
S121	LVDS1_3-	DSI1_D3-	eDP1_TX3-
S108	LVDS1_CLK+	DSI1_CLK+	eDP1_AUX+
S109	LVDS1_CLK-	DSI1_CLK-	eDP1_AUX-
S116	LCD1_VDD_EN	LCD1_VDD_EN	LCD1_VDD_EN
S107	LCD1_BKLT_EN	LCD1_BKLT_EN	LCD1_BKLT_EN
S122	LCD1_BKLT_PWM	LCD1_BKLT_PWM	LCD1_BKLT_PWM
S113		DSI1_TE	eDP1_HPD
S139	I2C_LCD_CLK	I2C_LCD_CLK	I2C_LCD_CLK
S140	I2C_LCD_DAT	I2C_LCD_DAT	I2C_LCD_DAT

4.3.1.1 DSI0 mode

Name	Pin #	Description	I/O		Name	Pin #	Description
DSI0_D0+ DSI0_D0- DSI0_D1+ DSI0_D1- DSI0_D2+ DSI0_D2- DSI0_D3+ DSI0_D3-	S125 S126 S128 S129 S131 S132 S137 S138	Primary DSI panel differential pair data lines	O D-PHY		Runtime		No blocking capacitors or termination required. Layout for 90 Ohms differential impedance.
DSI0_CLK+ DSI0_CLK-	S134 S135	Primary DSI panel differential pair clock lines	O D-PHY		Runtime		
LCD0_VDD_EN	S133	Primary panel power enable	O CMOS	1.8V	Runtime		Active high
LCD0_BKLT_EN	S127	Primary panel backlight enable	O CMOS	1.8V	Runtime		Active high
LCD0_BKLT_PWM	S141	Primary panel brightness control through pulse width modulation (PWM)	O CMOS	1.8V	Runtime		Through pulse width modulation (PWM)
DSI0_TE	S144	Primary DSI panel tearing effect signal	I CMOS	1.8V	Runtime	1M PD	
I2C_LCD_DAT	S140	DDC data line used for flat panel detection and control	I/O OD CMOS	1.8V	Runtime	PU 2k2	
I2C_LCD_CK	S139	DDC clock line used for flat panel detection and control	O OD CMOS	1.8V	Runtime	PU 2k2	
DSI1_D0+ DSI1_D0- DSI1_D1+ DSI1_D1- DSI1_D2+ DSI1_D2- DSI1_D3+ DSI1_D3-	S111 S112 S114 S115 S117 S118 S120 S121	Secondary DSI differential pair data lines	O LVDS D-PHY		Runtime		Not supported
DSI1_CLK+ DSI1_CLK-	S108 S109	Secondary DSI differential pair clock lines.	O LVDS D-PHY		Runtime		Not supported
LCD1_VDD_EN	S116	Secondary panel power enable, active high	O CMOS	1.8V	Runtime		Not supported
LCD1_BKLT_EN	S107	Secondary panel backlight enable, active high	O CMOS	1.8V	Runtime		Not supported

Name	Pin #	Description	I/O		Name	Pin #	Description
LCD1_BKLT_PWM	S122	Secondary panel brightness control through pulse width modulation (PWM)	O CMOS	1.8V	Runtime		Not supported
DSI1_TE	S113	Secondary DSI panel tearing effect signal	I CMOS	1.8V	Runtime		Not supported
I2C_LCD_DAT	S140	DDC data line used for flat panel detection and control	I/O OD CMOS	1.8V	Runtime	PU 2k2	Possible conflict if 2 DSI panels are used
I2C_LCD_CK	S139	DDC clock line used for flat panel detection and control	O OD CMOS	1.8V	Runtime	PU 2k2	Possible conflict if 2 DSI panels are used

4.3.1.2 eDP0 mode

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
eDP0_TX0+ eDP0_TX0- eDP0_TX1+ eDP0_TX1- eDP0_TX2+ eDP0_TX2- eDP0_TX3+ eDP0_TX3-	S125 S126 S128 S129 S131 S132 S137 S138	Primary 4-lane eDP differential pair data lines	O LVDS DP		Runtime		AC coupled off module
eDP0_AUX+ eDP0_AUX-	S134 S135	Primary bidirectional channel used for link management and device control	O LVDS DP		Runtime		AC coupled off module
LCD0_VDD_EN	S133	Primary panel power enable, active high	O CMOS	1.8V	Runtime		
LCD0_BKLT_EN	S127	Primary panel backlight enable, active high	O CMOS	1.8V	Runtime		
LCD0_BKLT_PWM	S141	Primary panel brightness control through pulse width modulation (PWM)	O CMOS	1.8V	Runtime		

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
eDP0_HPD	S144	Detection of Hot Plug / Unplug of primary eDP display and notification of the link layer.	I CMOS	1.8V	Runtime		Module must tolerate high level in stand-by mode
I2C_LCD_DAT	S140	I2C data to read LCD display EDID EEPROMs. Possible EDID EEPROM address conflicts may occur if multiple displays are implemented	I/O — OD CMOS	1.8V	Runtime	PU-2k2	Possible conflict if 2 panels are used
I2C_LCD_CK	S139	I2C clock to read LCD display EDID EEPROMs	O — OD CMOS	1.8V	Runtime	PU-2k2	Possible conflict if 2 panels are used

4.4 Secondary Display Interface

4.4.1.1 HDMI mode

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
HDMI_D2+ HDMI_D2- HDMI_D1+ HDMI_D1- HDMI_D0+ HDMI_D0-	P92 P93 P95 P96 P98 P99	HDMI port, differential pair data lines	O TMDS HDMI		Runtime		AC coupled off module
HDMI_CK+ HDMI_CK-	P101 P102	HDMI port, differential pair clock lines	O TMDS HDMI		Runtime		AC coupled off module
HDMI_CTRL_CK	P105	I2C_CLK line dedicated to HDMI	O OD COMS	1.8V	Runtime	PU 100K	Level shifter FET and 5V PU resistor shall be placed between the Module and the HDMI connector. Stronger pull-up is demanded to the carrier board. The pull-ups may be part of an integrated HDMI ESD protection and control-line level shift device, such as the Texas Instruments TPD12S016. If discrete Carrier pull-ups are used, the value depends on the individual carrier board implementation.
HDMI_CTRL_DAT	P106	I2C_DAT line dedicated to HDMI	I/O OD CMOS	1.8V	Runtime	PU 100K	Level shifter FET and 5V PU resistor shall be placed between the Module and the HDMI connector. Stronger pull-up is demanded to the carrier board. The pull-ups may be part of an integrated HDMI ESD protection and control-line level shift device, such as the Texas Instruments TPD12S016. If discrete Carrier pull-ups are used, the value depends on the individual carrier board implementation.

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
HDMI_HPD	P104	HDMI Hot plug active high detection signal that serves as an interrupt request	I CMOS	1.8V	Runtime	PD 1M	Important: Module shall tolerate high level in stand-by mode

4.4.1.2 DP mode

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
DP1_LANE0+ DP1_LANE0- DP1_LANE1+ DP1_LANE1- DP1_LANE2+ DP1_LANE2- DP1_LANE3+ DP1_LANE3-	P92 P93 P95 P96 P98 P99 P101 P102	Secondary DP port differential pair data lines	O LVDS DP		Runtime		AC coupled off module
DP1_AUX+	P105	Secondary DP port bidirectional channel used for link management and device control	I/O LVDS DP		Runtime	PD 100k	AC coupled off module
DP1_AUX-	P106	Secondary DP port bidirectional channel used for link management and device control	I/O LVDS DP		Runtime	PU 100k	AC coupled off module
DP1_HPD	P104	DP Hot Plug Detect input	I CMOS	1.8V	Runtime	PD 1M	Module must tolerate high level in stand-by mode
DP1_AUX_SEL	P107	Strapping signal to enable either HDMI or DP output	I CMOS	1.8V	Runtime	PD 1M	Pulled to GND on Carrier for DP operation in Dual Mode (DP++) implementations. Driven to 1.8V on carrier for HDMI mode. Module must tolerate high level in stand-by mode

4.4.2 MIPI Camera Support

4.4.2.1 CSI0 (2 lanes)

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
CSI0_RX0+ CSI0_RX0- CSI0_RX1+ CSI0_RX1-	S11 S12 S14 S15	CSI0 differential input (point to point)	I D-PHY / I M-PHY		Runtime		
CSI0_CK+ CSI0_CK-	S8 S9	CSI0 differential clock input (point to point)	I D-PHY		Runtime		
I2C_CAM0_DAT /CSI0_TX-	S7	I2C data for serial camera data support link or differential data lane	I/O OD CMOS / O M-PHY	1.8V	Runtime	PU 2.2K	MIPI-CSI 2.0 uses I2C_CAM0_DAT which requires PU MIPI-CSI 3.0 uses CSI0_TX-, no PU required
I2C_CAM0_CK / CSI0_TX+	S5	I2C clock for serial camera data support link or differential data lane	O OD CMOS / O M-PHY	1.8V	Runtime	PU 2.2K	MIPI-CSI 2.0 uses I2C_CAM0_CK which requires PU MIPI-CSI 3.0 uses CSI0_TX+, no PU required
CAM0_PWR# / GPIO0	P108	Camera 0 Power Enable, active low output.	O CMOS	1.8V	Runtime		Shared with GPIO0
CAM0_RST# / GPIO2	P110	Camera 0 reset, active low output	O CMOS	1.8V	Runtime		Shared with GPIO2
CAM_MCK	S6	Master clock output	O CMOS	1.8V	Runtime		

4.4.2.2 CSI1 (4 lanes)

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
CSI1_RX0+ CSI1_RX0- CSI1_RX1+ CSI1_RX1- CSI1_RX2+ CSI1_RX2- CSI1_RX3+ CSI1_RX3-	P7 P8 P10 P11 P13 P14 P16 P17	CSI1 differential input	I LVDS D-PHY / I LVDS M-PHY		Runtime		
CSI1_CK+ CSI1_CK-	P3 P4	CSI1 differential clock input (point to point)	I LVDS D-PHY		Runtime		
I2C_CAM1_DAT / CSI1_TX-	S2	I2C data for serial camera data support link or differential data lane	I/O OD CMOS / O LVDS M-PHY	1.8V	Runtime	PU 2.2K	MIPI-CSI 2.0 uses I2C_CAM0_DAT which requires PU MIPI-CSI 3.0 uses CSI0_TX-, no PU required
I2C_CAM1_CK / CSI1_TX+	S1	I2C clock for serial camera data support link or differential data lane	O OD CMOS / O LVDS M-PHY	1.8V	Runtime	PU 2.2K	MIPI-CSI 2.0 uses I2C_CAM0_CK which requires PU MIPI-CSI 3.0 uses CSI0_TX+, no PU required
CAM1_PWR# / GPIO1	P109	Camera 1 Power Enable, active low output.	O CMOS	1.8V	Runtime		Shared with GPIO1
CAM1_RST# / GPIO3	P111	Camera 1 reset, active low output	O CMOS	1.8V	Runtime		Shared with GPIO 3
CAM_MCK	S6	Master clock output	O CMOS	1.8V	Runtime		



Note: MediaTek has support for up to 3 cameras. The 3rd camera goes to a feature connector on the module as CSI2.

4.4.3 I²S (Audio)

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
I2S0_LRCK	S39	I2S0 Left & Right synchronization clock	I/O CMOS	1.8V	Runtime		Module Output if CPU acts in Master Mode Module Input if CPU acts in Slave Mode
I2S0_SDOUT	S40	I2S0 Digital audio Output	O CMOS	1.8V	Runtime		
I2S0_SDIN	S41	I2S0 Digital audio Input	I CMOS	1.8V	Runtime		
I2S0_CK	S42	I2S0 Digital audio clock	I/O CMOS	1.8V	Runtime		Module Output if CPU acts in Master Mode Module Input if CPU acts in Slave Mode
AUDIO_MCK	S38	Master clock output to I2S codec(s)	O CMOS	1.8V	Runtime		Shared with I2S2



Note: Support for I2S1 signalling has been removed during update to SMARC 2.0 specification

4.4.4 USB ports

The OTG port comes straight from SoC, other ports are derived from a USB3.1/2.0 SS hub (SOC has 2x USB2.0, 1x USB3.1

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
USB0+ USB0-	P60 P61	USB differential data pairs for port 0	I/O USB	USB	Standby		From SOC
USB0_EN_OC#	P62	USB over-current sense for port 0	I/O OD CMOS	3.3V ^{note 1}	Standby	PU 10k	Pulled low by Module OD driver to disable USB0 power. Pulled low by Carrier OD driver to indicate over-current situation.
USB0_VBUS_DET	P63	USB port 0 host power detection, when this port is used as a device.	I USB VBUS 5V	USB VBUS 5V	Standby		When this Port is used as a device it can be connected to a USB client port VBUS pin
USB0_OTG_ID	P64	Input pin to announce OTG device insertion on USB 2.0 port			Standby		Resistor value to ground according to USB specification
USB1+ USB1-	P65 P66	USB differential data pairs for port 1	I/O USB	USB	Standby		From SOC
USB1_EN_OC#	P67	USB over-current sense for port 1	I/O OD CMOS	3.3V ^{note 1}	Standby	PU 10k	Pulled low by Module OD driver to disable USB1 power. Pulled low by Carrier OD driver to indicate over-current situation.
USB2+ USB2-	P69 P70	USB differential data pairs for port 2	I/O USB	USB	Standby		From USB 3.1 Hub
USB2_SSRX+ USB2_SSRX-	S74 S75	Receive signal differential pairs for SuperSpeed on port 2	I USB SS	USB SS	Standby		DC blocking capacitors 100nF shall be placed on the Carrier
USB2_SSTX+ USB2_SSTX-	S71 S72	Transmit signal differential pairs for SuperSpeed on port 2	O USB SS	USB SS	Standby		DC blocking capacitors 100nF shall be placed on the Carrier
USB2_EN_OC#	P71	USB over-current sense for port 2	I/O OD CMOS	3.3V ^{note 1}	Standby	PU 10k	Pulled low by Module OD driver to disable USB2 power. Pulled low by Carrier OD driver to indicate over-current situation.
USB3+ USB3-	S68 S69	USB differential data pairs for port 3	I/O USB	USB	Standby		From USB 3.1 HUB

USB3_SSRX+ USB3_SSRX-	S65 S66	Receive signal differential pairs for SuperSpeed on port 3	I USB SS	USB SS	Standby		DC blocking capacitors 100nF shall be placed on the Carrier
USB3_SSTX+ USB3_SSTX-	S62 S63	Transmit signal differential pairs for SuperSpeed on port 3	O USB SS	USB SS	Standby		DC blocking capacitors 100nF shall be placed on the Carrier
USB3_EN_OC#	P74	USB over-current sense for port 3	I/O OD CMOS	3.3V ^{note 1}	Standby	PU 10k	Pulled low by Module OD driver to disable USB3 power. Pulled low by Carrier OD driver to indicate over-current situation.
USB3_VBUS_DET	S37	USB port 3 host power detection, when this port is used as a device.	↓ USB VBUS 5V	USB VBUS 5V	Standby	-	-
USB3_OTG_ID	S104	Input pin to announce OTG device insertion on USB 3.0 port	↓ CMOS	3.3V	Standby	-	-
USB4+ USB4-	S35 S36	USB differential data pairs for port 4	I/O USB	USB	Standby		From USB 3.1 HUB
USB4_EN_OC#	P76	USB over-current sense for port 4	I/O OD CMOS	3.3V ^{note 1}	Standby	PU 10k	Pulled low by Module OD driver to disable USB4 power. Pulled low by Carrier OD driver to indicate over-current situation.
USB5+ USB5-	S59 S60	USB differential data pairs for port 5	I/O USB	USB	Standby	-	
USB5_EN_OC#	S55	USB over-current sense for port 5	I/O OD CMOS	3.3V ^{note 1}	Standby	PU 10k	Pulled low by Module OD driver to disable USB5 power. Pulled low by Carrier OD driver to indicate over-current situation.

**Note:**

1. 3.3V or switched 3.3V — when an USB channel is not used, then USB[0:5]_EN_OC# pull-up rails may be held at GND to prevent current leak.
2. USB0 directly connects to the SoC and offers OTG, others share bandwidth through an USB 2.0/3.1 hub.

4.4.4.1 PCIe Ports

LEC-MTK-i1200 has several mixing options to provide different PCIe configurations:

- Single lane PCIe A, Dual lane PCIe B

- Single lane PCIe A,B,C

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
PCIE_A_TX+ PCIE_A_TX-	P89 P90	Differential PCIe link A transmit data pair	O LVDS PCIE		Runtime		Series AC coupled on module
PCIE_A_RX+ PCIE_A_RX-	P86 P87	Differential PCIe link A receive data pair	I LVDS PCIE		Runtime		Series AC coupled off module
PCIE_A_REFCK+ PCIE_A_REFCK-	P83 P84	Differential PCIe Link A reference clock output	O LVDS PCIE		Runtime		
PCIE_A_RST#	P75	PCIe Port A reset output	O CMOS	3.3V	Runtime		
PCIE_A_CKREQ#	P78	PCIe Port A clock request	I OD CMOS	3.3V	Runtime		Can be used for power saving mode on PCIe - Pulled up or terminated on Module
PCIE_B_TX+ PCIE_B_TX-	S90 S91	Differential PCIe link B transmit data pair	O LVDS PCIE		Runtime		Series AC coupled on module
PCIE_B_RX+ PCIE_B_RX-	S87 S88	Differential PCIe link B receive data pair	I LVDS PCIE		Runtime		Series AC coupled off module
PCIE_B_REFCK+ PCIE_B_REFCK-	S84 S85	Differential PCIe Link B reference clock output	O LVDS PCIE		Runtime		
PCIE_B_RST#	S76	PCIe Port B reset output	O CMOS	3.3V	Runtime		
PCIE_B_CKREQ#	P77	PCIe Port B clock request	I OD CMOS	3.3V	Runtime		Can be used for power saving mode on PCIe - Pulled up or terminated on Module

4.4.5 LAN Ports

4.4.5.1 First LAN (GBE0)

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments																												
GBE0_MDI0+ GBE0_MDI0- GBE0_MDI1+ GBE0_MDI1- GBE0_MDI2+ GBE0_MDI2- GBE0_MDI3+ GBE0_MDI3-	P30 P29 P27 P26 P24 P23 P20 P19	Differential Pair Signals for External Transformer Carrier Series Termination: Magnetics Module appropriate for 10/100/1000 GBE transceivers Carrier Parallel Termination: Secondary side center tap terminations appropriate for Gigabit Ethernet implementations	I/O GBE MDI		Standby		Gigabit Ethernet Controller 0: Media Dependent Interface Differential Pairs 0, 1, 2, 3. The MDI can operate in 1000, 100, and 10Mbit/sec modes. Some pairs are unused in some modes according to the following: <table><tr><td>1000</td><td>100</td><td>10</td><td>-</td></tr><tr><td>MDI[0]+/-</td><td>B1_DA+/-</td><td>TX+/-</td><td></td></tr><tr><td>TX+/-</td><td></td><td></td><td></td></tr><tr><td>MDI[1]+/-</td><td>B1_DB+/-</td><td>RX+/-</td><td></td></tr><tr><td>RX+/-</td><td></td><td></td><td></td></tr><tr><td>MDI[2]+/-</td><td>B1_DC+/-</td><td></td><td></td></tr><tr><td>MDI[3]+/-</td><td>B1_DD+/-</td><td></td><td></td></tr></table>	1000	100	10	-	MDI[0]+/-	B1_DA+/-	TX+/-		TX+/-				MDI[1]+/-	B1_DB+/-	RX+/-		RX+/-				MDI[2]+/-	B1_DC+/-			MDI[3]+/-	B1_DD+/-		
1000	100	10	-																																
MDI[0]+/-	B1_DA+/-	TX+/-																																	
TX+/-																																			
MDI[1]+/-	B1_DB+/-	RX+/-																																	
RX+/-																																			
MDI[2]+/-	B1_DC+/-																																		
MDI[3]+/-	B1_DD+/-																																		
GBE0_LINK100#	P21	Link Speed Indication LED for GBE 0 100Mbps	O OD CMOS	3.3V	Standby		Shall be able to sink 24mA or more Carrier LED current																												
GBE0_LINK1000#	P22	Link Speed Indication LED for GBE 0 1000Mbps	O OD CMOS	3.3V	Standby		Shall be able to sink 24mA or more Carrier LED current																												
GBE0_LINK_ACT#	P25	Link / Activity Indication LED Driven low on Link (10, 100 or 1000 mbps) Blinks on Activity	O OD CMOS	3.3V	Standby		Shall be able to sink 24mA or more Carrier LED current																												
GBE0_CTREF	P28	Center Tap reference voltage for Carrier board Ethernet magnetic (if required by the Module GBE PHY)	Analog	0 to 3.3V max	Standby	-	-																												
GBE0_SDP	P6	IEEE 1588 Trigger Signal. For hardware implementation of PTP (precision time protocol)	I/O CMOS	3.3V	Standby	-	-																												



Note 1: LAN_0 port comes from SoC RGMII interface while LAN_1 port derives from USB (optional)

4.4.5.2 Second LAN (GBE1)

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments																					
GBE1_MDI0+ GBE1_MDI0- GBE1_MDI1+ GBE1_MDI1- GBE1_MDI2+ GBE1_MDI2- GBE1_MDI3+ GBE1_MDI3-	S17 S18 S20 S21 S23 S24 S26 S27	Differential Pair Signals for External Transformer Carrier Series Termination: Magnetics Module appropriate for 10/100/1000 GBE transceivers Carrier Parallel Termination: Secondary side center tap terminations appropriate for Gigabit Ethernet implementations	I/O GBE MDI		Standby		Gigabit Ethernet Controller 1: Media Dependent Interface Differential Pairs 0, 1, 2, 3. The MDI can operate in 1000, 100, and 10Mbit/sec modes. Some pairs are unused in some modes according to the following: <table><tr><td>1000</td><td>100</td><td>10</td></tr><tr><td>MDI[0]+/-</td><td>B1_DA+/-</td><td>TX+/-</td></tr><tr><td>TX+/-</td><td></td><td></td></tr><tr><td>MDI[1]+/-</td><td>B1_DB+/-</td><td>RX+/-</td></tr><tr><td>RX+/-</td><td></td><td></td></tr><tr><td>MDI[2]+/-</td><td>B1_DC+/-</td><td></td></tr><tr><td>MDI[3]+/-</td><td>B1_DD+/-</td><td></td></tr></table>	1000	100	10	MDI[0]+/-	B1_DA+/-	TX+/-	TX+/-			MDI[1]+/-	B1_DB+/-	RX+/-	RX+/-			MDI[2]+/-	B1_DC+/-		MDI[3]+/-	B1_DD+/-	
1000	100	10																										
MDI[0]+/-	B1_DA+/-	TX+/-																										
TX+/-																												
MDI[1]+/-	B1_DB+/-	RX+/-																										
RX+/-																												
MDI[2]+/-	B1_DC+/-																											
MDI[3]+/-	B1_DD+/-																											
GBE1_LINK100#	S19	Link Speed Indication LED for GBE 1 100Mbps	O OD CMOS	3.3V	Standby		Shall be able to sink 24mA or more Carrier LED current																					
GBE1_LINK1000#	S22	Link Speed Indication LED for GBE 1 1000Mbps	O OD CMOS	3.3V	Standby		Shall be able to sink 24mA or more Carrier LED current																					
GBE1_LINK_ACT#	S31	Link / Activity Indication LED Driven low on Link (10, 100 or 1000 mbps) Blinks on Activity	O OD CMOS	3.3V	Standby		Shall be able to sink 24mA or more Carrier LED current																					
GBE1_CTREF	S28	Center Tap reference voltage for Carrier board Ethernet magnetic (if required by the Module GBE PHY)	Analog	0 to 3.3V max	Standby	-	-																					
GBE1_SDP	P5	IEEE 1588 Trigger Signal. For hardware implementation of PTP (precision time protocol)	IO CMOS	3.3V	Standby	-	-																					



Note: Second optional LAN port comes from USB 3.1

4.4.6 SDIO

The Carrier SDIO **may** be selected as the Boot Device

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
SDIO_D0 SDIO_D1 SDIO_D2 SDIO_D3	P39 P40 P41 P42	SDIO Data lines. These signals operate in push-pull mode.	I/O CMOS	1.8V or 3.3V	Runtime		SDIO controller will detect SD Cards voltage level (1.8V for UHS-I and 3.3V for standard) and adjust its I/O voltage level accordingly
SDIO_WP	P33	SDIO Write Protect. This signal denotes the state of the write-protect tab on SD cards.	I OD CMOS	3.3V	Runtime	PU 10k	Pulled up on module
SDIO_CMD	P34	SDIO Command/Response. This signal is used for card initialization and for command transfers. During initialization mode this signal is open drain. During command transfer this signal is in push-pull mode.	I/O CMOS	1.8V or 3.3V	Runtime		SDIO controller will detect SD Cards voltage level (1.8V for UHS-I and 3.3V for standard) and adjust its I/O voltage level accordingly
SDIO_CD#	P35	SDIO Card Detect. This signal indicates when a SDIO/MMC card is present.	I OD CMOS	3.3V	Runtime	PU 10k	Pulled up on module
SDIO_CK	P36	SDIO Clock. With each cycle of this signal a one-bit transfer on the command and each data line occurs.	O CMOS	1.8V or 3.3V	Runtime		
SDIO_PWR_EN	P37	SDIO Power Enable. This signal is used to enable the power being supplied to a SD/MMC card device.	O CMOS	3.3V	Runtime		should be driven low in STB Mode by the module

4.4.7 SPI

4.4.7.1 SPI0

SPI boot not supported

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
SPI0_CS0#	P43	SPI0 Master Chip Select 0	O CMOS	1.8V	Standby		This signal can be used to select carrier SPI as boot device
SPI0_CS1#	P31	SPI0 Master Chip Select 1	O CMOS	1.8V	Standby		
SPI0_CK	P44	SPI0 Clock	O CMOS	1.8V	Standby		
SPI0_DIN	P45	SPI0 Master input / Slave output	I CMOS	1.8V	Standby		also referred to as MISO
SPI0_DO	P46	SPI0 Master output / Slave input	O CMOS	1.8V	Standby		also referred to as MOSI

4.4.7.2 SPI1

SPI Mode

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
SPI1_CS0#	P45	SPI1 Master Chip Select 0	O CMOS	1.8V	Standby		This signal can be used to select carrier SPI as boot device. can also be used as ESPI_CS0#
SPI1_CS1#	P55	SPI1 Master Chip Select 1	O CMOS	1.8V	Standby		can also be used as ESPI_CS1#
SPI1_CK	P56	SPI1 Clock	O CMOS	1.8V	Standby		can also be used as ESPI_CK
SPI1_DIN	P57	SPI1 Master input / Slave output	I CMOS	1.8V	Standby		also referred to as MISO can also be used as ESPI_IO_1
SPI1_DO	P58	SPI1 Master output / Slave input	O CMOS	1.8V	Standby		also referred to as MOSI can also be used as ESPI_IO_0

4.4.8 GPIO

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
GPIO0 / CAM0_PWR#	P108	General purpose I/O pin 0.	I/O CMOS	1.8V	Runtime	PU 470K ¹	alternate use is Camera 0 Power Enable, active low output
GPIO1 / CAM1_PWR#	P109	General purpose I/O pin 1.	I/O CMOS	1.8V	Runtime	PU 470K ¹	alternate use is Camera 1 Power Enable, active low output
GPIO2 / CAM0_RST#	P110	General purpose I/O pin 2.	I/O CMOS	1.8V	Runtime	PU 470K ¹	alternate use is Camera 0 Reset, active low output
GPIO3 / CAM1_RST#	P111	General purpose I/O pin 3.	I/O CMOS	1.8V	Runtime	PU 470K ¹	alternate use is Camera 1 Reset, active low output
GPIO4 / HDA_RST#	P112	General purpose I/O pin 4.	I/O CMOS	1.8V	Runtime	PU 470K ¹	alternative use is HD Audio Reset, active low output
GPIO5 / PWM_OUT	P113	General purpose I/O pin 5.	I/O CMOS	1.8V	Runtime	PU 470K ¹	alternate use is PWM output
GPIO6 / TACHIN	P114	General purpose I/O pin 6.	I/O CMOS	1.8V	Runtime	PU 470K ¹	FAN Tachometer input (used with GPIO5 PWM_OUT)
GPIO7	P115	General purpose I/O pin 7.	I/O CMOS	1.8V	Runtime	PU 470K ¹	
GPIO8	P116	General purpose I/O pin 8.	I/O CMOS	1.8V	Runtime	PU 470K ¹	
GPIO9	P117	General purpose I/O pin 9.	I/O CMOS	1.8V	Runtime	PU 470K ¹	
GPIO10	P118	General purpose I/O pin 10.	I/O CMOS	1.8V	Runtime	PU 470K ¹	
GPIO11	P119	General purpose I/O pin 11.	I/O CMOS	1.8V	Runtime	PU 470K ¹	
GPIO12	S142	General purpose I/O pin 12	I/O CMOS	1.8V	Runtime	PU 470K ¹	advised as INT signal to any expander on carrier.
GPIO13	S123	General purpose I/O pin 13	I/O CMOS	1.8V	Runtime	PU 470K ¹	

 **Note:** Allows for in-SoC Pull-Ups. These can be $\leq 10k$. Max 2.2k PD should be implemented on Carrier when needing low levels.

4.4.9 CAN Bus

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
CAN0_TX	P143	CAN port 0 Transmit output	O CMOS	1.8V	Runtime		
CAN0_RX	P144	CAN port 0 Receive input	I CMOS	1.8V	Runtime		

4.4.10 Miscellaneous

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
TEST#	S157	Held Low by Carrier to Invoke Module Vendor Specific Test Functions	I OD CMOS	1.8 to 5 V	Runtime	PU	Module must implement PU but actual value is depended on particular Module design. Carrier Board should leave this pin floating for normal operation. Driven by OD on Carrier
WDT_TIME_OUT#	S145	Watch-Dog-Timer Output, low active.	O CMOS	1.8V	Runtime		
PWM_OUT / GPIO5	P113	Pulse Width Modulation (PWM) output	I/O CMOS	1.8V	Runtime	PU 470K	GPIO5 is the default pin configuration

4.4.11 Power and System Management

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
BATLOW#	S156	Battery low indication to Module. Carrier to float the line in inactive state.	I OD CMOS	1.8V to 5V	Standby/ Sleep	PU 10K	Driven by OD on Carrier. Pulled up on module.
CARRIER_PWR_ON	S154	Carrier Board circuits (apart from power management and power path circuits) should not be powered up until the Module asserts the CARRIER_PWR_ON signal.	O CMOS	1.8V	Standby		On x86 designs this pin should utilize a standby related power signal i.e. RSM_RST# or SLP_A# signal.
CARRIER_STBY#	S153	The Module shall drive this signal low when the system is in a standby power state.	O CMOS	1.8V	Standby		On x86 designs this pin should utilize the SUS_S3# signal.
CHARGER_PRSENT#	S152	Held low by Carrier if DC input for battery charger is present.	I OD CMOS	1.8V to 5V	Standby/ Sleep	PU 10K	Driven by OD on Carrier. Pulled up on module.
CHARGING#	S151	Held low by Carrier during battery charging. Carrier to float the line when charge is complete.	I OD CMOS	1.8V to 5V	Standby/ Sleep	PU 10K	Driven by OD on Carrier. Pulled up on module.
VIN_PWR_BAD#	S150	Power bad indication from Carrier Board. Module and Carrier power supplies (other than Module and Carrier power supervisory circuits) shall not be enabled while this signal is held low by the Carrier.	I OD CMOS	VDD_IN		PU 10K	Driven by OD on Carrier. Module must implement PU but actual value is depended on particular module design.
SLEEP#	S149	Sleep indicator from Carrier Board. May be sourced from user Sleep button or Carrier logic. Carrier to float the line in in-active state. Active low, level sensitive. Should be de-bounced on the Module.	I OD CMOS	1.8V to 5V	Standby	PU 10K	Driven by OD on Carrier. Pulled up on module.
LID#	S148	Lid open/close indication to Module. Low indicates lid closure (which system may use to initiate a sleep state). Carrier to float the line in in-active state. Active low, level sensitive. Should be de-bounced on the Module.	I OD CMOS	1.8V to 5V	Standby	PU 10K	Driven by OD on Carrier. Pulled up on module.
POWER_BTN#	P128	Power-button input from Carrier Board. Carrier to float the line in in-active state. Active low, level sensitive. Should be debounced on the Module.	I OD CMOS	1.8V to 5V	Standby	PU 10K	Driven by OD on Carrier. Pulled up on module.
RESET_OUT#	P126	General purpose reset output to Carrier board.	O CMOS	1.8V	Standby		

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
RESET_IN#	P127	Reset input from Carrier Board. Carrier drives low to force a Module reset, floats the line otherwise. This signal shall be level triggered during bootup to allow to stop booting of the module. After bootup it may act as an edge triggered signal.	I OD CMOS	1.8V to 5V	Standby	PU 10K	Driven by OD on Carrier. Pulled up on module.
I2C_PM_DAT	P122	Power management I2C bus DATA	I/O OD CMOS	1.8V	Standby/ Sleep	PU 2k2	On x86 systems these serve as SMB DATA. Pulled up on module.
I2C_PM_CLK	P121	Power management I2C bus CLK	O OD CMOS	1.8V	Standby/ Sleep	PU 2k2	On x86 systems these serve as SMB CLK. Pulled up on module.
SMB_ALERT_1V8#	P1	SMBus Alert# (interrupt) signal	I OD CMOS	1.8V to 5V	Standby/ Sleep	PU 2k2	only used on x86 design

4.4.12 Boot Select

Name	Pin #	Description	I/O Type	I/O Level	Power Domain	PU / PD	Comments
BOOT_SEL0# BOOT_SEL1# BOOT_SEL2#	P123 P124 P125	Input straps determine the Module boot	I OD CMOS	1.8V	Standby	PU 10K	Driven by OD on Carrier. Pulled up on module. Only boot from UFS is supported
FORCE_RECOV#	S155		I OD CMOS	1.8V	Standby	PU 10K	Driven by OD on Carrier. Pulled up on module. Low on this pin allows non-protected segments of Module boot device to be rewritten / restored from an external USB Host on Module USB0. The Module USB0 operates in Client Mode when in the Force Recovery function is invoked. Pulled high on the Module. For SOCs that do not implement a USB based Force Recovery functions, then a low on the Module FORCE_RECOV# pin may invoke the SOC native Force Recovery mode – such as over a Serial Port. For x86 systems this signal may be used to load BIOS defaults. Pulled up on Module. Driven by OD part on Carrier.

4.4.13 Power

Name	Pin #	Description	I/O Type	Power Rail / Tolerance	PU / PD	Comments
VDD_IN	P147, P148, P149, P150, P151, P152, P153, P154, P155, P156	Module power input voltage 4.75 min to 5.25V max	P Not defined within Signal Terminology Descriptions. Should we define a specific rail?	5V +/- 5%		
GND	P2, P9, P12, P15, P18, P32, P38, P47, P50, P53, P59, P68, P79, P82, P85, P88, P91, P94, P97, P100, P103, P120, P133, P142, S3, S10, S16, S25, S34, S47, S61, S64, S67, S70, S73, S80, S83, S86, S89, S92, S101, S110, S119, S124, S130, S136, S143, S158	Module signal and power return, and GND reference	P Not defined within Signal Terminolgy Descriptions. Should we define a specific rail?	Ground		
VDD_RTC	S147	Low current RTC circuit backup power – 3.0V nominal. May be sourced from a Carrier based Lithium cell or Super Cap.	P Not defined within Signal Terminology Descriptions. Should we define a specific rail?	[2 to 3.25] / 3.25V		

4.5 SMARC Pin-to-controller Mapping

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
P1	SMB_ALERT_1V8#	-	-	-	-	
P2	GND	-	-	-	-	
P3	CSI1_CK+	-	MIPI_CSI	MT8395	CSI0A_L2P	
P4	CSI1_CK-	-	MIPI_CSI	MT8395	CSI0A_L2N	
P5	GBE1_SDP	-	-	-	-	
P6	GBE0_SDP	-	GPIO / 3.3V	DP83867IRRGZR	GPIO_0	
P7	CSI1_RX0+	-	MIPI_CSI	MT8395	CSI0A_L1P	
P8	CSI1_RX0-	-	MIPI_CSI	MT8395	CSI0A_L1N	
P9	GND	-	-	-	-	
P10	CSI1_RX1+	-	MIPI_CSI	MT8395	CSI0B_L0P	
P11	CSI1_RX1-	-	MIPI_CSI	MT8395	CSI0B_L0N	
P12	GND	-	-	-	-	
P13	CSI1_RX2+	-	MIPI_CSI	MT8395	CSI0A_L0P	
P14	CSI1_RX2-	-	MIPI_CSI	MT8395	CSI0A_L0N	
P15	GND	-	-	-	-	
P16	CSI1_RX3+	-	MIPI_CSI	MT8395	CSI0B_L1P	
P17	CSI1_RX3-	-	MIPI_CSI	MT8395	CSI0B_L1N	
P18	GND	-	-	-	-	
P19	GBE0_MDI3-	-	GBE MDI	DP83867IRRGZR	TD_M_D	
P20	GBE0_MDI3+	-	GBE MDI	DP83867IRRGZR	TD_P_D	
P21	GBE0_LINK100#	-	GPIO / 3.3V	DP83867IRRGZR	LED_1	
P22	GBE0_LINK1000#	-	GPIO / 3.3V	DP83867IRRGZR	LED_2	
P23	GBE0_MDI2-	-	GBE MDI	DP83867IRRGZR	TD_M_C	
P24	GBE0_MDI2+	-	GBE MDI	DP83867IRRGZR	TD_P_C	
P25	GBE0_LINK_ACT#	-	GPIO / 3.3V	DP83867IRRGZR	LED_0	
P26	GBE0_MDI1-	-	GBE MDI	DP83867IRRGZR	TD_M_B	

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
P27	GBE0_MDI1+	-	GBE MDI	DP83867IRRGZR	TD_P_B	
P28	GBE0_CTREF	-	Analog / 3.3V	-	-	
P29	GBE0_MDI0-	-	GBE MDI	DP83867IRRGZR	TD_M_A	
P30	GBE0_MDI0+	-	GBE MDI	DP83867IRRGZR	TD_P_A	
P31	SPI0_CS1#	-	-	-	-	
P32	GND	-	-	-	-	
P33	SDIO_WP	-	SD / 1.8	MT8395	GPIO	ALT0
P34	SDIO_CMD	-	SD / 1.8/3.3V	MT8395	MSDC1_CMD	ALT1
P35	SDIO_CD#	-	SD / 1.8	MT8395	GPIO	ALT0
P36	SDIO_CK	-	SD / 1.8/3.3V	MT8395	MSDC1_CLK	ALT1
P37	SDIO_PWR_EN	-	GPIO / 3.3V	MT8395	GPIO	ALT0
P38	GND	-	-	-	-	
P39	SDIO_D0	-	SD / 1.8/3.3V	MT8395	MSDC1_DAT0	ALT1
P40	SDIO_D1	-	SD / 1.8/3.3V	MT8395	MSDC1_DAT1	ALT1
P41	SDIO_D2	-	SD / 1.8/3.3V	MT8395	MSDC1_DAT2	ALT1
P42	SDIO_D3	-	SD / 1.8/3.3V	MT8395	MSDC1_DAT3	ALT1
P43	SPI0_CS0#	-	SPI / 1.8V	MT8395	SPIM1_CSB	ALT1
P44	SPI0_CK	-	SPI / 1.8V	MT8395	SPIM1_CLK	ALT1
P45	SPI0_DIN	-	SPI / 1.8V	MT8395	SPIM1_MI	ALT1
P46	SPI0_DO	-	SPI / 1.8V	MT8395	SPIM1_MO	ALT1
P47	GND	-	-	-	-	
P48	SATA_TX+	-	-	-	-	
P49	SATA_TX-	-	-	-	-	
P50	GND	-	-	-	-	
P51	SATA_RX+	-	-	-	-	
P52	SATA_RX-	-	-	-	-	
P53	GND	-	-	-	-	
P54	ESPI_CS0# / SPI1_CS0#	-	SPI / 1.8V	MT8395	SPIM2_CSB	ALT1
P55	ESPI_CS1# / SPI1_CS1#	-	-	-	-	
P56	ESPI_CK / SPI1_CK	-	SPI / 1.8V	MT8395	SPIM2_CLK	ALT1

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
P57	ESPI_IO_1 / SPI1_DIN	-	SPI / 1.8V	MT8395	SPIM2_MI	ALT1
P58	ESPI_IO_0 / SPI1_DO	-	SPI / 1.8V	MT8395	SPIM2_MO	ALT1
P59	GND	-	-	-	-	
P60	USB0+	-	USB / 3.3V	MT8395	USB_DP_P0	
P61	USB0-	-	USB / 3.3V	MT8395	USB_DM_P0	
P62	USB0_EN_OC#	PU-10K	GPIO / 3.3V	SX1509BIULTRT	I/O1	
P63	USB0_VBUS_DET	-	USB / 3.3V	MT6365	CHRDDET_B	
P64	USB0_OTG_ID	-	USB / 1.8V	MT8395	USB_IDDIG	
P65	USB1+	-	USB / 3.3V	MT8395	USB_DP_P3	
P66	USB1-	-	USB / 3.3V	MT8395	USB_DM_P3	
P67	USB1_EN_OC#	-	GPIO / 3.3V	SX1509BIULTRT	I/O2	
P68	GND	-	-	-	-	
P69	USB2+	-	USB / 3.3V	USB5807C/KD	USB2DN_DP3	
P70	USB2-	-	USB / 3.3V	USB5807C/KD	USB2DN_DM3	
P71	USB2_EN_OC#	-	GPIO / 3.3V	USB5807C/KD	PRT_CTL3/GPIO19	
P72	RSVD	-	-	-	-	
P73	RSVD	-	-	-	-	
P74	USB3_EN_OC#	-	GPIO / 3.3V	USB5807C/KD	PRT_CTL4/GANG_PWR/GPIO20	
P75	PCIE_A_RST#	-	GPIO / 3.3V	MT8395	PCIE_PERESET_N	ALT1
P76	USB4_EN_OC#	-	GPIO / 3.3V	USB5807C/KD	PRT_CTL5/GPIO21	
P77	PCIE_B_CKREQ#	-	-	-	-	
P78	PCIE_A_CKREQ#	PU-10K	PCIE / 3.3V	MT8395	PCIE_CLKREQ_N	ALT1
P79	GND	-	-	-	-	
P80	PCIE_C_REFCK+	-	-	-	-	
P81	PCIE_C_REFCK-	-	-	-	-	
P82	GND	-	-	-	-	
P83	PCIE_A_REFCK+	-	PCIe	MT8395	PCIEG3_CLKP	
P84	PCIE_A_REFCK-	-	PCIe	MT8395	PCIEG3_CLKN	
P85	GND	-	-	-	-	
P86	PCIE_A_RX+	-	PCIe	MT8395	PCIEG3_LN0_RXP	

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
P87	PCIE_A_RX-	-	PCIe	MT8395	PCIEG3_LN0_RXN	
P88	GND	-	-	-	-	
P89	PCIE_A_TX+	Serial-0.22uF	PCIe	MT8395	PCIEG3_LN0_TXP	
P90	PCIE_A_TX-	Serial-0.22uF	PCIe	MT8395	PCIEG3_LN0_TXN	
P91	GND	-	-	-	-	
P92	HDMI_D2+ / DP1_LANE0+	-	HDMI/DP	HD3SS215IRTQR	DC0P	
P93	HDMI_D2- / DP1_LANE0-	-	HDMI/DP	HD3SS215IRTQR	DC0N	
P94	GND	-	-	-	-	
P95	HDMI_D1+ / DP1_LANE1+	-	HDMI/DP	HD3SS215IRTQR	DC1P	
P96	HDMI_D1- / DP1_LANE1-	-	HDMI/DP	HD3SS215IRTQR	DC1N	
P97	GND	-	-	-	-	
P98	HDMI_D0+ / DP1_LANE2+	-	HDMI/DP	HD3SS215IRTQR	DC2P	
P99	HDMI_D0- / DP1_LANE2-	-	HDMI/DP	HD3SS215IRTQR	DC2N	
P100	GND	-	-	-	-	
P101	HDMI_CK+ / DP1_LANE3+	-	HDMI/DP	HD3SS215IRTQR	DC3P	
P102	HDMI_CK- / DP1_LANE3-	-	HDMI/DP	HD3SS215IRTQR	DC3N	
P103	GND	-	-	-	-	
P104	HDMI_HPD / DP1_HPD	-	HDMI	HD3SS215IRTQR	A1	
P105	HDMI_CTRL_CK / DP1_AUX+	-	HDMI/DP	TS5A23159RSER	MUX	
P106	HDMI_CTRL_DAT / DP1_AUX-	-	HDMI/DP	TS5A23159RSER	MUX	
P107	DP1_AUX_SEL	-	GPIO / 1.8V	Logic IC	-	
P108	GPIO0 / CAM0_PWR#	PU-470K	GPIO / 1.8V	MT8395	GPIO	ALTO
P109	GPIO1 / CAM1_PWR#	PU-470K	GPIO / 1.8V	MT8395	GPIO	ALTO
P110	GPIO2 / CAM0_RST#	PU-470K	GPIO / 1.8V	MT8395	GPIO	ALTO
P111	GPIO3 / CAM1_RST#	PU-470K	GPIO / 1.8V	MT8395	GPIO	ALTO
P112	GPIO4 / HDA_RST#	PU-470K	GPIO / 1.8V	MT8395	GPIO	ALTO
P113	GPIO5 / PWM_OUT	PU-470K	GPIO / 1.8V	MT8395	GPIO	ALTO
P114	GPIO6 / TACHIN		GPIO / 1.8V	MT8395	GPIO	ALTO
P115	GPIO7	PU-470K	GPIO / 1.8V	SX1509BIULTRT	I/O1	

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
P116	GPIO8	PU-470K	GPIO / 1.8V	SX1509BIULTRT	I/O2	
P117	GPIO9	PU-470K	GPIO / 1.8V	SX1509BIULTRT	I/O3	
P118	GPIO10	PU-470K	GPIO / 1.8V	SX1509BIULTRT	I/O4	
P119	GPIO11	PU-470K	GPIO / 1.8V	SX1509BIULTRT	I/O13	
P120	GND	-	-	-	-	
P121	I2C_PM_CK	PU-2k2	I2C / 1.8V	MT8395	SCL2	ALT1
P122	I2C_PM_DAT	PU-2k2	I2C / 1.8V	MT8395	SDA2	ALT1
P123	BOOT_SEL0#	PU-10K	GPIO / 1.8V	From Carrier board	-	
P124	BOOT_SEL1#	PU-10K	GPIO / 1.8V	From Carrier board	-	
P125	BOOT_SEL2#	PU-10K	GPIO / 1.8V	From Carrier board	-	
P126	RESET_OUT#	-	GPIO / 1.8V	Logic IC	-	
P127	RESET_IN#	PU-10K	GPIO / 1.8V	Logic IC	-	
P128	POWER_BTN#	PU-10K	GPIO / 1.8V	From Carrier board	-	
P129	SER0_TX	-	UART / 1.8V	MT8395	UTXD2	ALT6
P130	SER0_RX	-	UART / 1.8V	MT8395	URXD2	ALT6
P131	SER0_RTS#	-	UART / 1.8V	MT8395	URTS2	ALT6
P132	SER0_CTS#	-	UART / 1.8V	MT8395	UCTS2	ALT6
P133	GND	-	-	-	-	
P134	SER1_TX	-	UART / 1.8V	MT8395	UART0_TXD	ALT1
P135	SER1_RX	-	UART / 1.8V	MT8395	UART0_RXD	ALT1
P136	SER2_TX	-	UART / 1.8V	FT230XQ-R	TXD	
P137	SER2_RX	-	UART / 1.8V	FT230XQ-R	RXD	
P138	SER2_RTS#	-	UART / 1.8V	FT230XQ-R	/RTS	
P139	SER2_CTS#	-	UART / 1.8V	FT230XQ-R	/CTS	
P140	SER3_TX	-	UART / 1.8V	MT8395	UTXD3	ALT4
P141	SER3_RX	-	UART / 1.8V	MT8395	URXD3	ALT4
P142	GND	-	-	-	-	
P143	CAN0_TX	-	CAN / 1.8V	MCP2518FDT-E/QBB	TXCAN	
P144	CAN0_RX	-	CAN / 1.8V	MCP2518FDT-E/QBB	RXCAN	

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
P145	CAN1_TX	-	-	-	-	
P146	CAN1_RX	-	-	-	-	
P147	VDD_IN	-	-	From Carrier board	-	
P148	VDD_IN	-	-	From Carrier board	-	
P149	VDD_IN	-	-	From Carrier board	-	
P150	VDD_IN	-	-	From Carrier board	-	
P151	VDD_IN	-	-	From Carrier board	-	
P152	VDD_IN	-	-	From Carrier board	-	
P153	VDD_IN	-	-	From Carrier board	-	
P154	VDD_IN	-	-	From Carrier board	-	
P155	VDD_IN	-	-	From Carrier board	-	
P156	VDD_IN	-	-	From Carrier board	-	
S1	CSI1_TX+ / I2C_CAM1_CK	PU-2k2	I2C / 1.8V	Camera Module		
S2	CSI1_TX- / I2C_CAM1_DAT	PU-2k2	I2C / 1.8V	Camera Module		
S3	GND	-	-	-	-	
S4	RSVD	-	-	-	-	
S5	CSI0_TX- / I2C_CAM0_CK	-	I2C / 1.8V	MT8395	SCL0	ALT1
S6	CAM_MCK	-	CAM / 1.8V	MT8395	CMMCLK0	ALT1
S7	CSI0_TX+ / I2C_CAM0_DAT	-	I2C / 1.8V	MT8395	SDA0	ALT1
S8	CSI0_CK+	-	CSI	MT8395	CSI1A_L1P_T0C	
S9	CSI0_CK-	-	CSI	MT8395	CSI1A_L1N_T1A	
S10	GND	-	-	-	-	
S11	CSI0_RX0+	-	CSI	MT8395	CSI1A_L0P_T0A	
S12	CSI0_RX0-	-	CSI	MT8395	CSI1A_L0N_T0B	
S13	GND	-	-	-	-	
S14	CSI0_RX1+	-	CSI	MT8395	CSI1A_L2P_T1B	
S15	CSI0_RX1-	-	CSI	MT8395	CSI1A_L2N_T1C	
S16	GND	-	-	-	-	
S17	GBE1_MDIO+	-	GBE MDI	LAN7800/VSX	TR0P	
S18	GBE1_MDIO-	-	GBE MDI	LAN7800/VSX	TR0N	

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
S19	GBE1_LINK100#	-	GPIO / 3.3V	LAN7800/VSX	LED1	
S20	GBE1_MDI1+	-	GBE MDI	LAN7800/VSX	TR1P	
S21	GBE1_MDI1-	-	GBE MDI	LAN7800/VSX	TR1N	
S22	GBE1_LINK1000#	-	GPIO / 3.3V	LAN7800/VSX	LED0	
S23	GBE1_MDI2+	-	GBE MDI	LAN7800/VSX	TR2P	
S24	GBE1_MDI2-	-	GBE MDI	LAN7800/VSX	TR2N	
S25	GND	-	-	-	-	
S26	GBE1_MDI3+	-	GBE MDI	LAN7800/VSX	TR3P	
S27	GBE1_MDI3-	-	GBE MDI	LAN7800/VSX	TR3N	
S28	GBE1_CTREF	-	Analog / 3.3V	-	-	
S29	PCIE_D_TX+ / SERDES_1_TX+	-	-	-	-	
S30	PCIE_D_TX- / SERDES_1_TX-	-	-	-	-	
S31	GBE1_LINK_ACT#	-	GPIO / 3.3V	LAN7800/VSX	LED2	
S32	PCIE_D_RX+ / SERDES_1_RX+	-	-	-	-	
S33	PCIE_D_RX- / SERDES_1_RX-	-	-	-	-	
S34	GND	-	-	-	-	
S35	USB4+	-	USB / 3.3V	USB5807C/KD	USB2DN_DP5	
S36	USB4-	-	USB / 3.3V	USB5807C/KD	USB2DN_DM5	
S37	USB3_VBUS_DET	-	-	-	-	
S38	AUDIO_MCK	-	I2S / 1.8V	MT8395	I2SO1_MCK	ALT1
S39	I2SO_LRCK	-	I2S / 1.8V	MT8395	I2SO1_WS	ALT1
S40	I2SO_SDOUT	-	I2S/ 1.8V	MT8395	I2SO1_D0	ALT1
S41	I2SO_SDIN	-	I2S / 1.8V	MT8395	I2SIN_D0	ALT1
S42	I2SO_CK	-	I2S / 1.8V	MT8395	I2SO1_BCK	ALT1
S43	ESPI_ALERT0#	-	-	-	-	
S44	ESPI_ALERT1#	-	-	-	-	
S45	MDIO_CLK	-	-	-	-	
S46	MDIO_DAT	-	-	-	-	
S47	GND	-	-	-	-	
S48	I2C_GP_CK	PU-2.2K	I2C / 1.8V	MT8395	SCL3	ALT1

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
S49	I2C_GP_DAT	PU-2.2K	I2C / 1.8V	MT8395	SDA3	ALT1
S50	HDA_SYNC / I2S2_LRCK	-	-	-	-	
S51	HDA_SDO / I2S2_SDOUT	-	-	-	-	
S52	HDA_SDI / I2S2_SDIN	-	-	-	-	
S53	HDA_CK / I2S2_CK	-	-	-	-	
S54	SATA_ACT#	-	-	-	-	
S55	USB5_EN_OC#	-	GPIO / 3.3V	USB5807C/KD	PRT_CTL6/GPIO22	
S56	ESPI_IO_2	-	-	-	-	
S57	ESPI_IO_3	-	-	-	-	
S58	ESPI_RESET#	-	-	-	-	
S59	USB5+	-	USB / 3.3V	USB5807C/KD	USB2DN_DP6	
S60	USB5-	-	USB / 3.3V	USB5807C/KD	USB2DN_DM6	
S61	GND	-	-	-	-	
S62	USB3_SSTX+	-	USB / 3.3V	USB5807C/KD	USB3DN_TXDP4	
S63	USB3_SSTX-	-	USB / 3.3V	USB5807C/KD	USB3DN_TXDM4	
S64	GND	-	-	-	-	
S65	USB3_SSRX+	-	USB / 3.3V	USB5807C/KD	USB3DN_RXDP4	
S66	USB3_SSRX-	-	USB / 3.3V	USB5807C/KD	USB3DN_RXDM4	
S67	GND	-	-	-	-	
S68	USB3+	-	USB / 3.3V	USB5807C/KD	USB2DN_DP4	
S69	USB3-	-	USB / 3.3V	USB5807C/KD	USB2DN_DM4	
S70	GND	-	-	-	-	
S71	USB2_SSTX+	-	USB / 3.3V	USB5807C/KD	USB3DN_TXDP3	
S72	USB2_SSTX-	-	USB / 3.3V	USB5807C/KD	USB3DN_TXDM3	
S73	GND	-	-	-	-	
S74	USB2_SSRX+	-	USB / 3.3V	USB5807C/KD	USB3DN_RXDP3	
S75	USB2_SSRX-	-	USB / 3.3V	USB5807C/KD	USB3DN_RXDM3	
S76	PCIE_B_RST#	-	-	-	-	
S77	PCIE_C_RST#	-	-	-	-	
S78	PCIE_C_RX+ / SERDES_2_RX+	-	PCIE	PI3PCIE3415AZHEX	DOa+	

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
S79	PCIE_C_RX- / SERDES_2_RX-	-	PCIE	PI3PCIE3415AZHEX	DOa-	
S80	GND	-	-	-	-	
S81	PCIE_C_TX+ / SERDES_2_TX+	-	PCIE	PI3PCIE3415AZHEX	COa+	
S82	PCIE_C_TX- / SERDES_2_TX-	-	PCIE	PI3PCIE3415AZHEX	COa-	
S83	GND	-	-	-	-	
S84	PCIE_B_REFCK+	-	PCIE	9DBV0441AKILF	DIF0	
S85	PCIE_B_REFCK-	-	PCIE	9DBV0441AKILF	/DIF0	
S86	GND	-	-	-	-	
S87	PCIE_B_RX+	-	PCIE	PI3PCIE3415AZHEX	BI+	
S88	PCIE_B_RX-	-	PCIE	PI3PCIE3415AZHEX	BI-	
S89	GND	-	-	-	-	
S90	PCIE_B_TX+	-	PCIE	PI3PCIE3415AZHEX	AI+	
S91	PCIE_B_TX-	-	PCIE	PI3PCIE3415AZHEX	AI-	
S92	GND	-	-	-	-	
S93	DP0_LANE0+	-	-	-	-	
S94	DP0_LANE0-	-	-	-	-	
S95	DP0_AUX_SEL	-	-	-	-	
S96	DP0_LANE1+	-	-	-	-	
S97	DP0_LANE1-	-	-	-	-	
S98	DP0_HPD	-	-	-	-	
S99	DP0_LANE2+	-	-	-	-	
S100	DP0_LANE2-	-	-	-	-	
S101	GND	-	-	-	-	
S102	DP0_LANE3+	-	-	-	-	
S103	DP0_LANE3-	-	-	-	-	
S104	USB3_OTG_ID	-	-	-	-	
S105	DP0_AUX+	-	-	-	-	
S106	DP0_AUX-	-	-	-	-	
S107	LCD1_BKLT_EN	-	GPIO / 1.8V	MT8395	GPIO	ALTO

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
S108	LVDS1_CK+ / eDP1_AUX+ / DSI1_CLK+	-	DSI	MT8395	DSI1_CKP_T1B	
S109	LVDS1_CK- / eDP1_AUX- / DSI1_CLK-	-	DSI	MT8395	DSI1_CKN_T1C	
S110	GND	-	-	-	-	
S111	LVDS1_0+ / eDP1_TX0+ / DSI1_D0+	-	DSI	MT8395	DSI1_D0P_T0C	
S112	LVDS1_0- / eDP1_TX0- / DSI1_D0-	-	DSI	MT8395	DSI1_D0N_T1A	
S113	eDP1_HPD / DSI1_TE	-	DSI	MT8395	DSI1_TE	ALT2
S114	LVDS1_1+ / eDP1_TX1+ / DSI1_D1+	-	DSI	MT8395	DSI1_D1P_T2A	
S115	LVDS1_1- / eDP1_TX1- / DSI1_D1-	-	DSI	MT8395	DSI1_D1N_T2B	
S116	LCD1_VDD_EN	-	GPIO / 1.8V	MT8395	GPIO	ALT0
S117	LVDS1_2+ / eDP1_TX2+ / DSI1_D2+	-	DSI	MT8395	DSI1_D2P_T0A	
S118	LVDS1_2- / eDP1_TX2- / DSI1_D2-	-	DSI	MT8395	DSI1_D2N_T0B	
S119	GND	-	-	-	-	
S120	LVDS1_3+ / eDP1_TX3+ / DSI1_D3+	-	DSI	MT8395	DSI1_D3P_T2C	
S121	LVDS1_3- / eDP1_TX3- / DSI1_D3-	-	DSI	MT8395	DSI1_D3N	
S122	LCD1_BKLT_PWM	-	PWM / 1.8V	MT8395	DISP_PWM1	ALT2
S123	GPIO13	PU-470K	GPIO / 1.8V	SX1509BIULTRT	I/O15	
S124	GND	-	-	-	-	
S125	LVDS0_0+ / eDP0_TX0+ / DSI0_D0+	-	eDP/DSI	TMUXHS4212IRKSR	A1P	
S126	LVDS0_0- / eDP0_TX0- / DSI0_D0-	-	eDP/DSI	TMUXHS4212IRKSR	A1N	
S127	LCD0_BKLT_EN	-	GPIO / 1.8V	MT8395	GPIO	ALT0
S128	LVDS0_1+ / eDP0_TX1+ / DSI0_D1+	-	eDP/DSI	TMUXHS4212IRKSR	A0P	

	SMARC Signal Name	Module Termination	Type/Tolerance	Controller	Controller Pin Name	I/O Mux default
S129	LVDS0_1- / eDP0_TX1- / DSIO_D1-	-	eDP/DSI	TMUXHS4212IRKSR	A0N	
S130	GND	-	-	-	-	
S131	LVDS0_2+ / eDP0_TX2+ / DSIO_D2+	-	eDP/DSI	TMUXHS4212IRKSR	A1P	
S132	LVDS0_2- / eDP0_TX2- / DSIO_D2-	-	eDP/DSI	TMUXHS4212IRKSR	A1N	
S133	LCD0_VDD_EN	-	GPIO /1.8V	MT8395	GPIO	ALT0
S134	LVDS0_CK+ / eDP0_AUX+ / DSIO_CLK+	-	eDP/DSI	TMUXHS4212IRKSR	A0P	
S135	LVDS0_CK- / eDP0_AUX- / DSIO_CLK-	-	eDP/DSI	TMUXHS4212IRKSR	A0N	
S136	GND	-	-	-	-	
S137	LVDS0_3+ / eDP0_TX3+ / DSIO_D3+	-	eDP/DSI	TMUXHS4212IRKSR	A0P	
S138	LVDS0_3- / eDP0_TX3- / DSIO_D3-	-	eDP/DSI	TMUXHS4212IRKSR	A0N	
S139	I2C_LCD_CK	PU-2.2K	I2C / 1.8V	MT8395	SCL0	ALT1
S140	I2C_LCD_DAT	PU-2.2K	I2C / 1.8V	MT8395	SDA0	ALT1
S141	LCD0_BKLT_PWM	-	PWM / 1.8V	MT8395	DISP_PWM0	ALT1
S142	GPIO12	PU-470K	GPIO / 1.8V	SX1509BIULTRT	I/O14	
S143	GND	-	-	-	-	
S144	eDP0_HPD / DSIO_TE		eDP/DSI	TMUXHS4212IRKSR	A1P	
S145	WDT_TIME_OUT#	-	GPIO / 1.8V	MT8395	PMIC_WATCHDOG	
S146	PCIE_WAKE#	PU-10K	GPIO / 3.3V	Logic IC	-	
S147	VDD_RTC	-	Analog / 2V~3.25V	From Carrier board	-	
S148	LID#	PU-10K	GPIO / 1.8V	SX1509BIULTRT	I/O12	
S149	SLEEP#	PU-10K	GPIO / 1.8V	SX1509BIULTRT	I/O8	
S150	VIN_PWR_BAD#	PU-10K	GPIO / 5V	From Carrier board	-	
S151	CHARGING#	PU-10K	GPIO / 1.8V	From Carrier board	-	
S152	CHARGER_PRSENT#	PU-10K	GPIO / 1.8V	From Carrier board	-	
S153	CARRIER_STBY#	-	GPIO / 1.8V	Logic IC	-	

5. Software Support

5.1 Yocto

Latest release supported

5.2 Android

Android 13

5.3 AI

Supports Arm NN and TFlite models

6. Mechanical

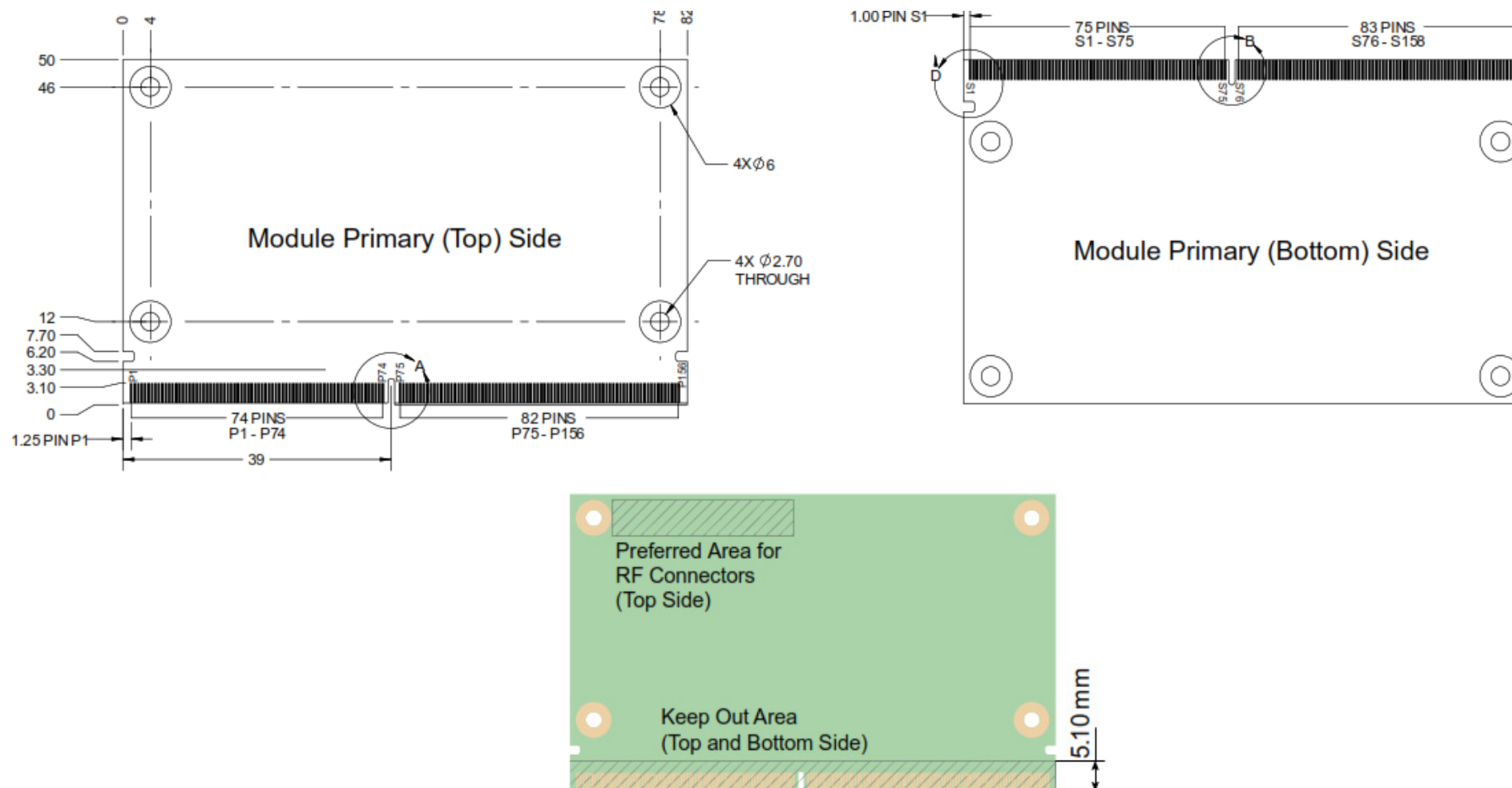


Figure 3 – Module Dimensions

7. Thermal Solutions

7.1 Heatspreader: HTS

Sustainable temperature range with high performance LAB copper heatsink
with high airflow = -40 to 85°C ambient

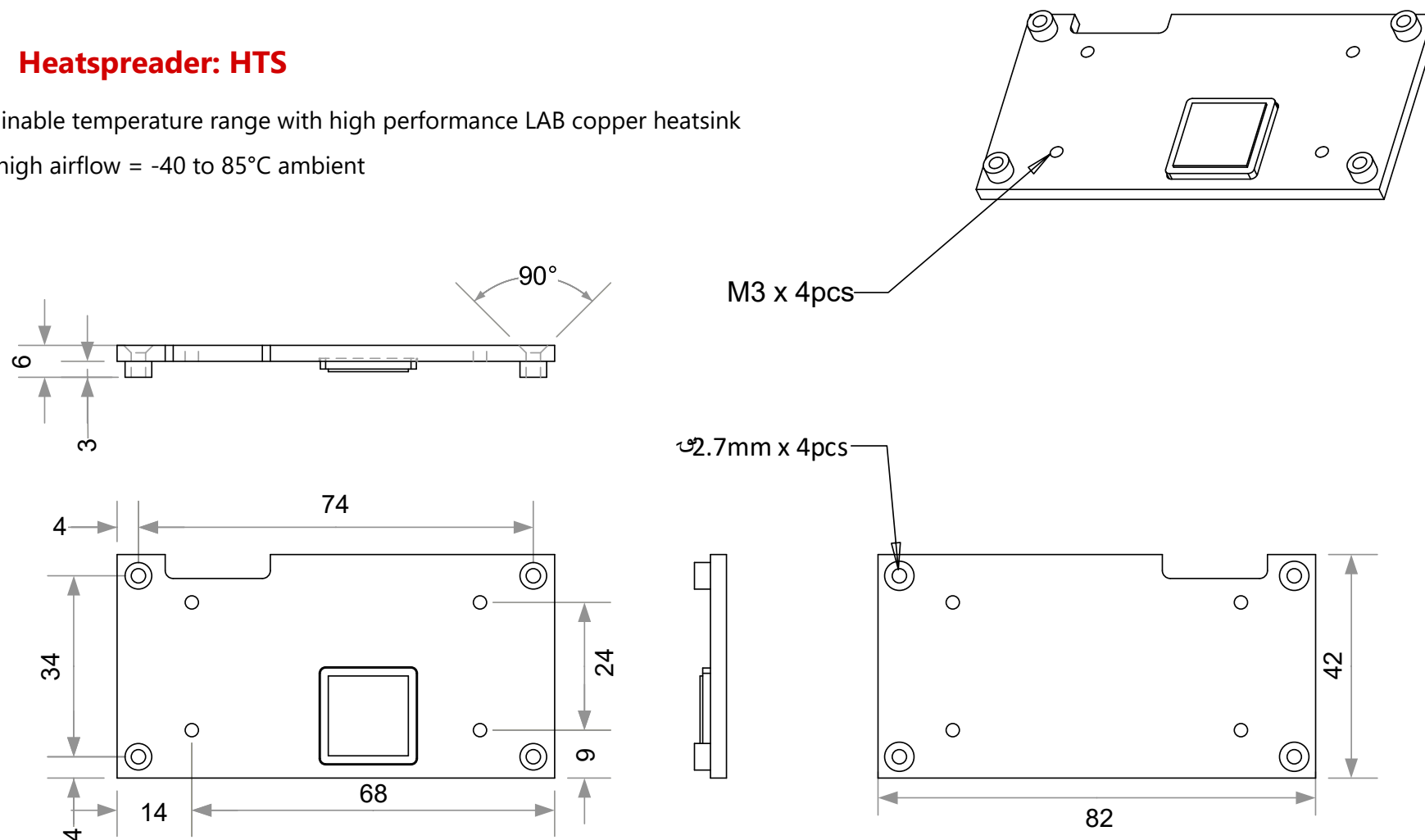


Figure 4 – Heatspreader HTS

7.2 Heatsink: THS

Sustainable temperature range with moderate airflow = 0 to 60°C ambient

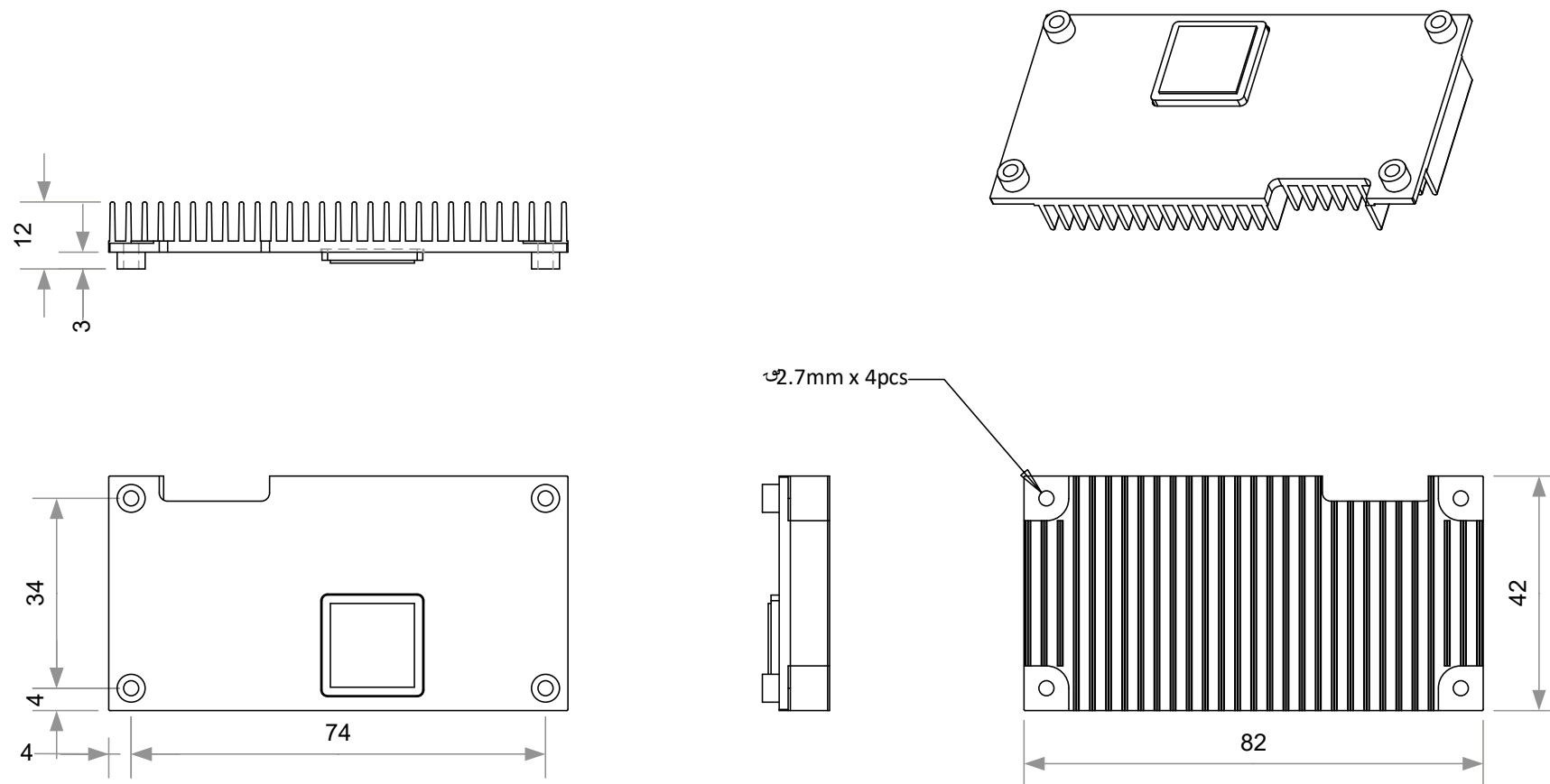


Figure 5 – Heatsink THS